

Elektronik

Active Components

EITA10

Iman Ghotbi

April 2025



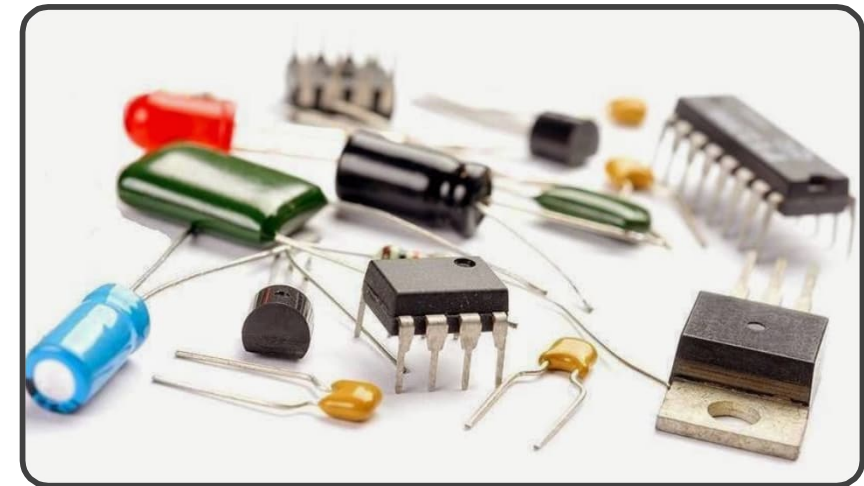
Active and Passive Components

- **Passive components**

- Resistors, capacitors, inductors, etc.
- Do not need to be activated (always working)
- Wide linear range

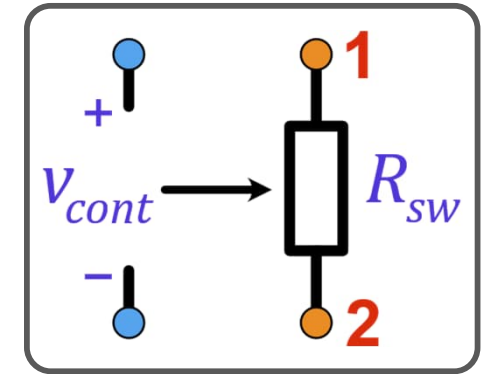
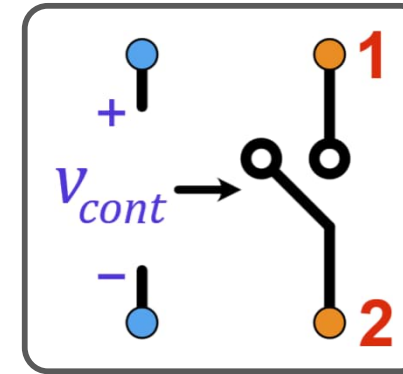
- **Active components**

- Diodes, transistors, ICs, LEDs, etc.
- Must be activated.
- Multiple modes of operation
- Control current flow and voltage distribution
- Generally nonlinear



An Ideal Electronically-Controlled Switch

- A two-state device
- Having four terminals
- The **resistance** between 1 and 2 is controlled by the voltage applied to the Gate.

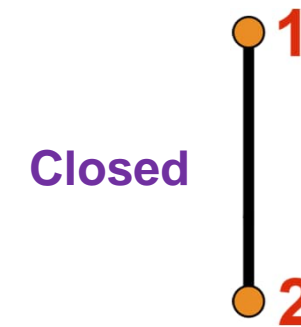
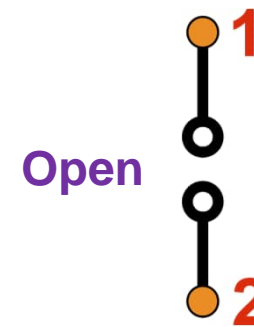


- **OFF state:**

- $v_{cont} < 0 \Rightarrow R_{sw} \rightarrow \infty$
- Open, perfect isolation between 1 and 2

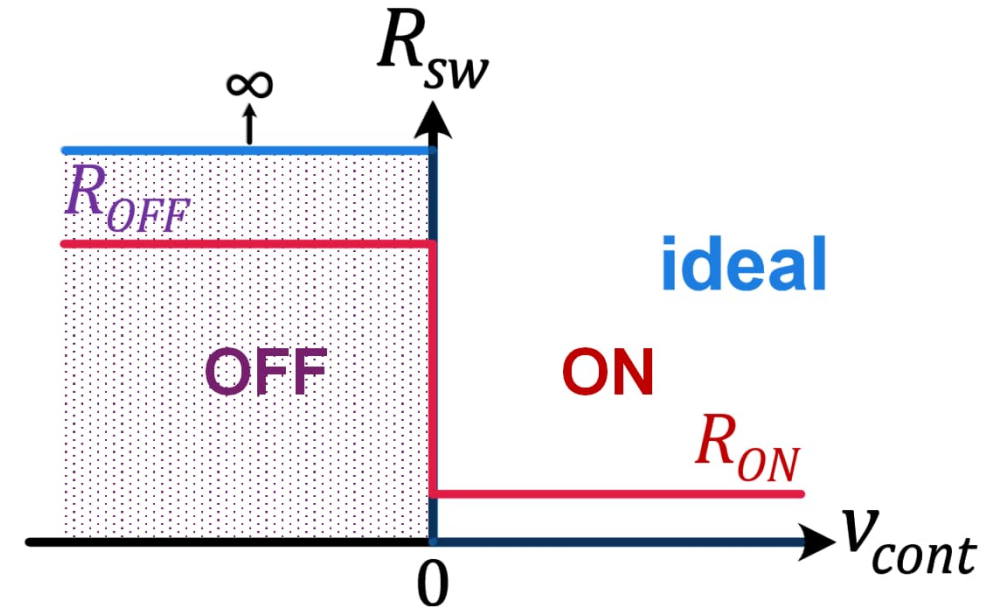
- **ON state:**

- $v_{cont} \geq 0 \Rightarrow R_{sw} = 0$
- Closed, short-circuit between 1 and 2



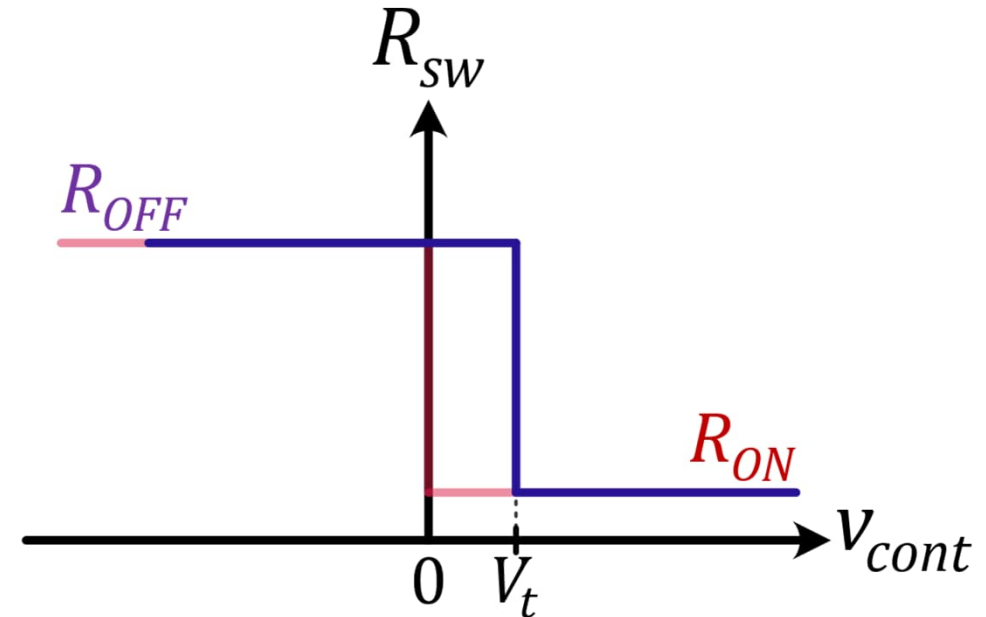
Realistic Switch

- Finite OFF-resistance (R_{OFF})
- Imperfect ON-resistance (R_{ON})
 - Voltage drop
 - Power loss and noise generation
- **Threshold** voltage (V_t)



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- **Gradual transition** from OFF to ON

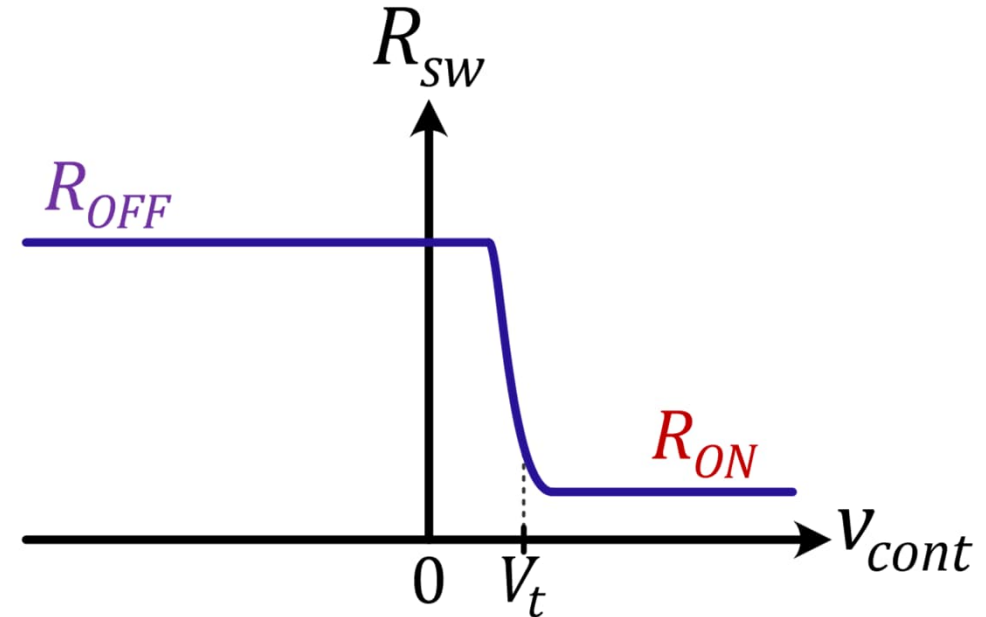


$$R_{sw} = \begin{cases} R_{OFF} & ; v_{cont} < V_t \\ R_{ON} & ; v_{cont} \geq V_t \end{cases}$$



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- Parasitic capacitances



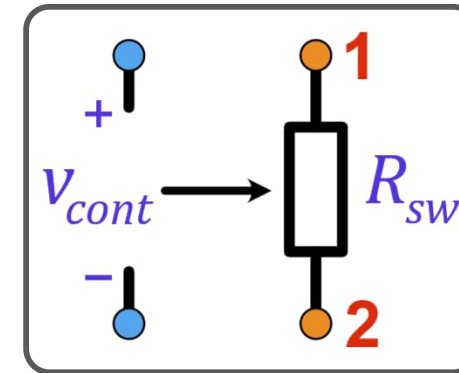
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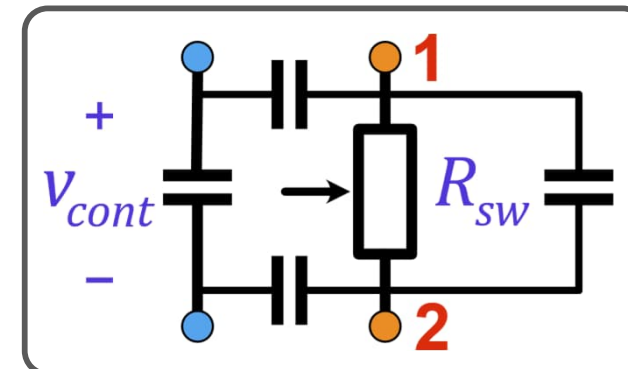
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 - Power loss and noise generation
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- Parasitic capacitances
- Equivalent high-frequency RC-circuit
 - Delay ($\tau = RC$)
 - Limited sampling frequency (f_s)

Low-Frequency Model

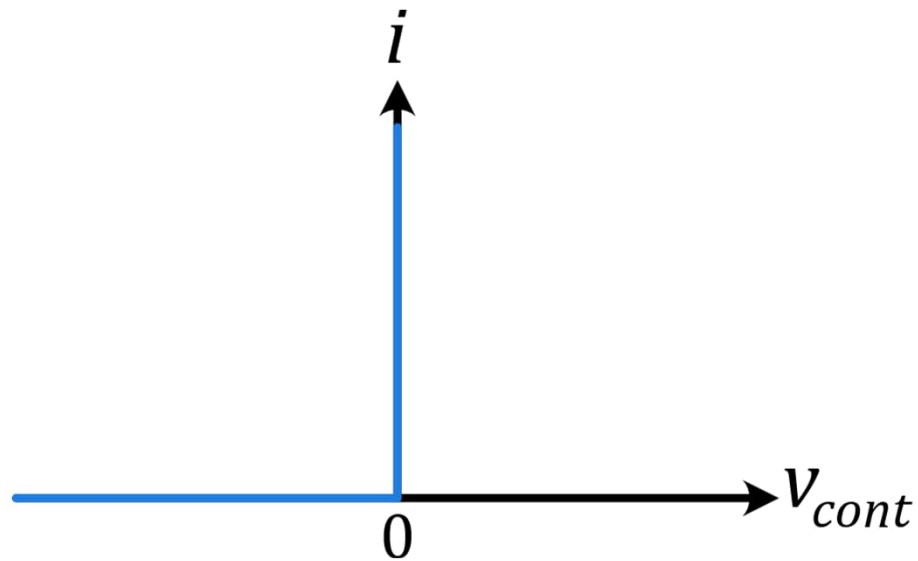
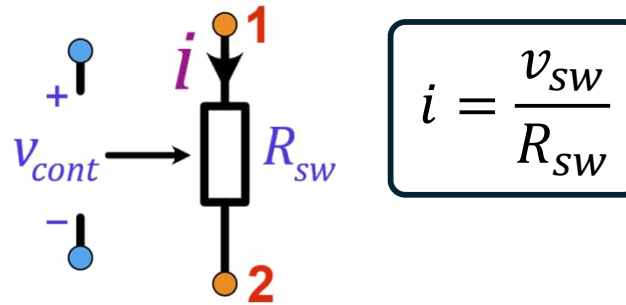


High-Frequency Model

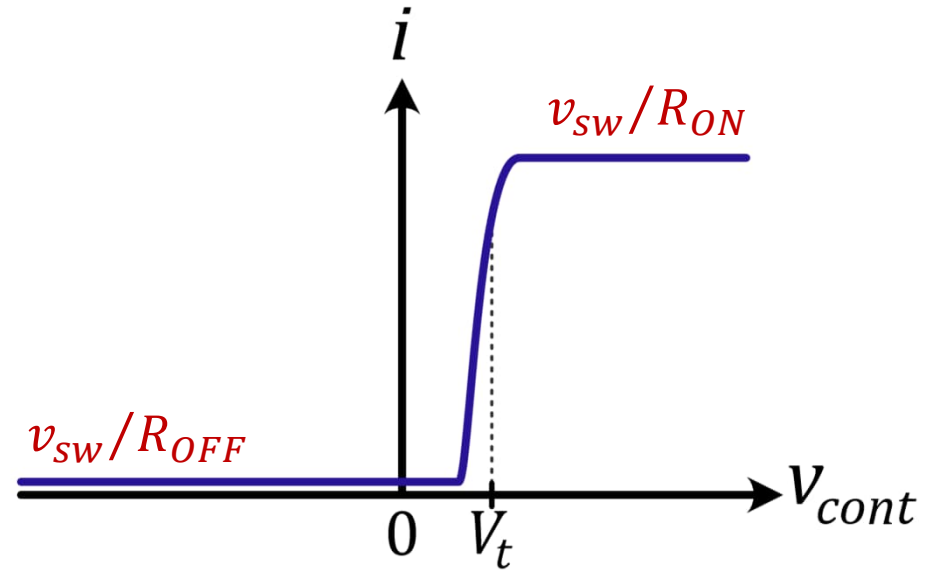


$i - v$ Characteristic of a Switch

- For a constant $v_{sw} = v_1 - v_2$



ideal

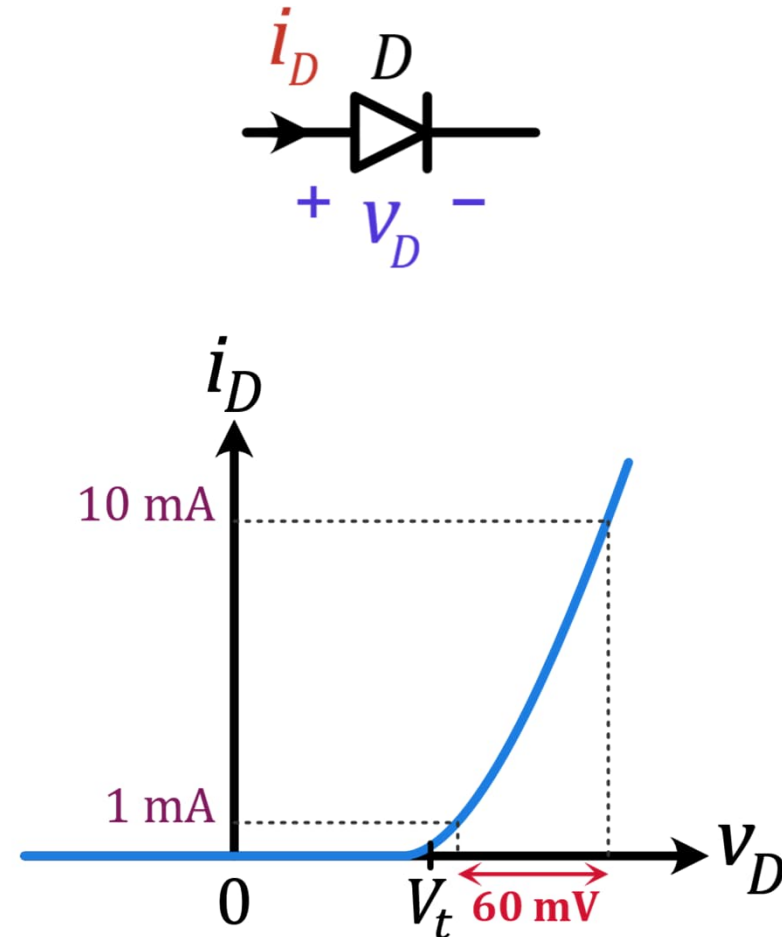


Practical



Diode, a Self-Controlled Switch

- The control voltage is the same as the voltage across the device ($v_{cont} = v_D$).
- **ON state**
 - $v_D \geq V_t \approx 0.7\text{ V}$
 - v_D remains **almost constant**, no matter what current flows! (~60 mV per decade)
 - $R_{ON} \approx \frac{25\text{ mV}}{I_D}$ (at room temperature)
- **OFF state**
 - $v_D < V_t$
 - $R_{OFF} \approx 100\text{ to }1000\text{ M}\Omega$

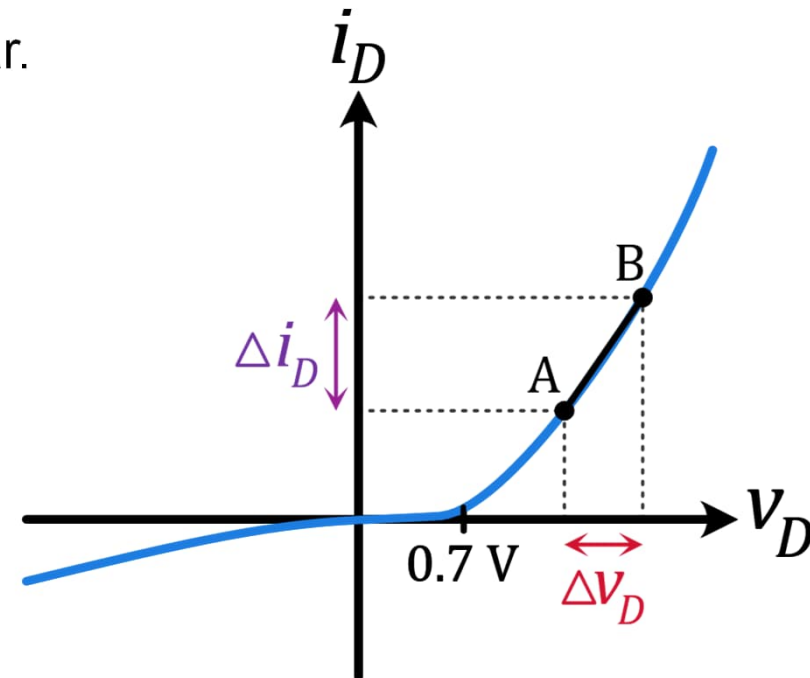


Pause and Ponder 1

A group of students have measured and plotted the $i - v$ characteristic diagram of a diode. Can you help them calculate the values of R_{ON} and R_{OFF} ?

- By definition, $R_D = \frac{v_D}{i_D}$; however, diode is nonlinear.
- Linearization in a region of operation:

$$R_D = \frac{\Delta v_D}{\Delta i_D}$$



Pause and Ponder 1

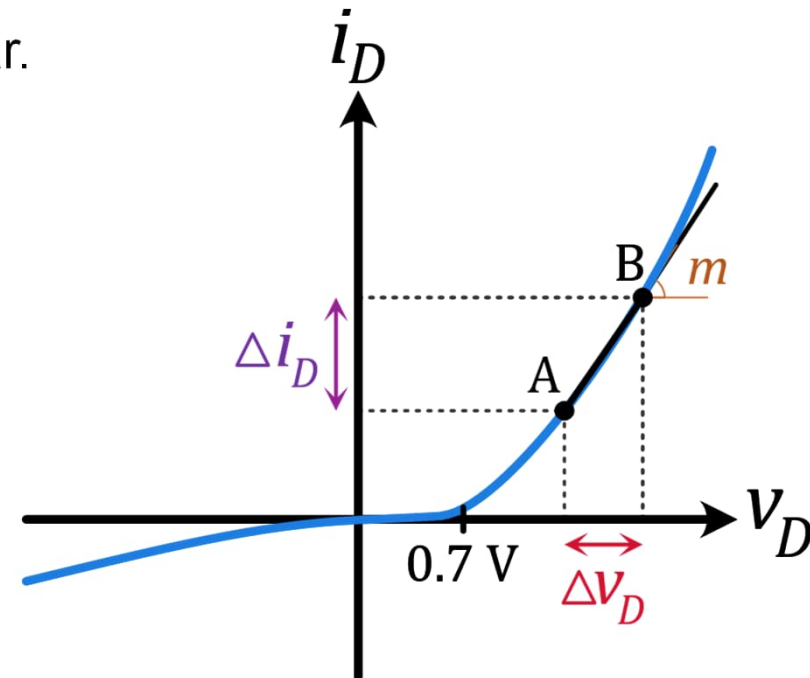
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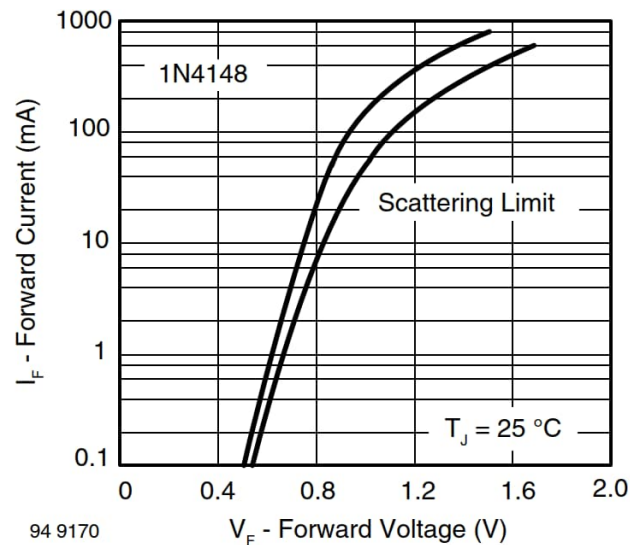
- Linearization at a certain point:

$$R_D = \left(\frac{di_D}{dv_D} \right)^{-1}$$

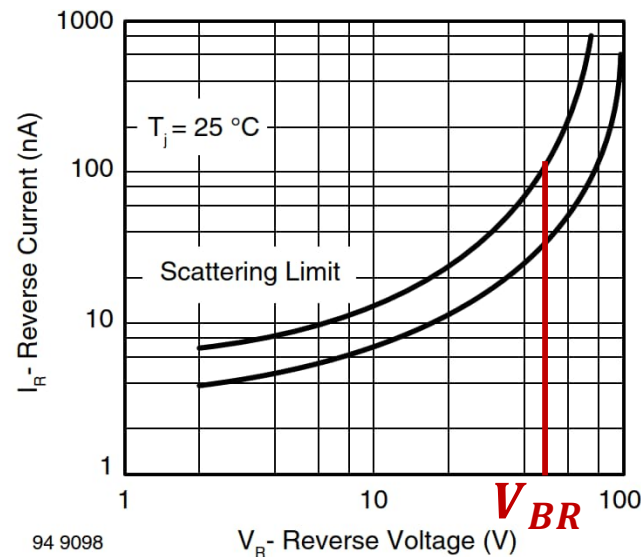


1N4148, a Commercial Diode

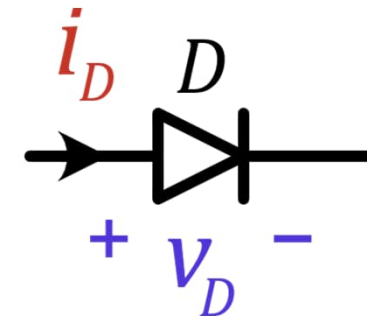
ON State $v_D \geq V_t$
(Forward Bias)



OFF State $v_D \geq V_t$
(Reverse Bias)



Anode Cathode



- Logarithmic scale to highlight **subthreshold** ($0 < v_D < V_t$) current

- Breakdown voltage (V_{BR}) = 75 V
- Sharp increase in reverse current



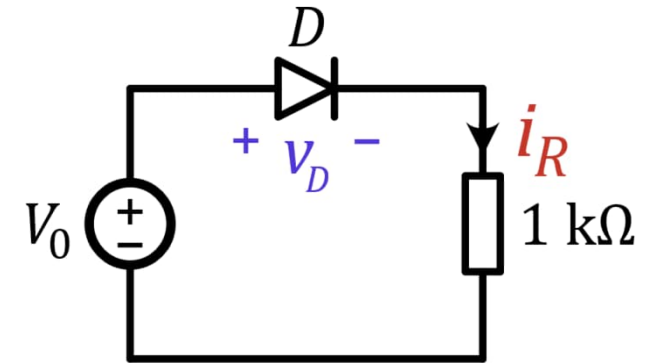
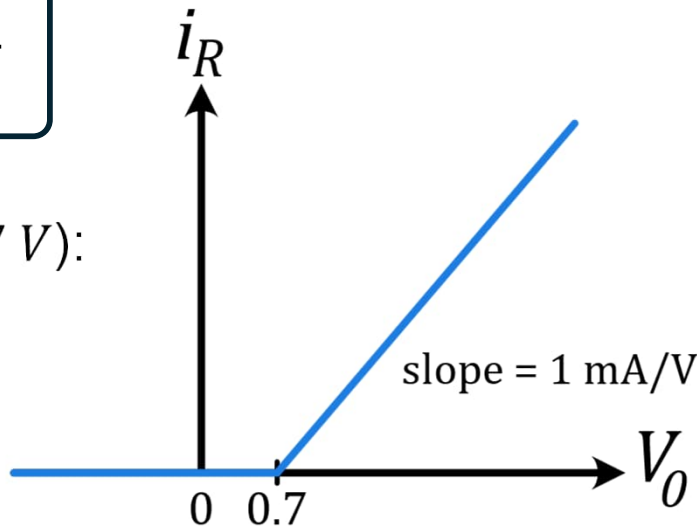
Diode Circuits – Example 1

- Complete the table below. ($V_t = 0.7\text{ V}$, $V_{BR} = 75\text{ V}$)
- When diode conducts ($v_D \geq 0.7\text{ V}$):

$$i_R = \frac{V_0 - v_D}{R} \approx \frac{V_0 - 0.7}{1000}$$

- When diode is OFF ($v_D < 0.7\text{ V}$):

$$i_R = i_D = 0$$

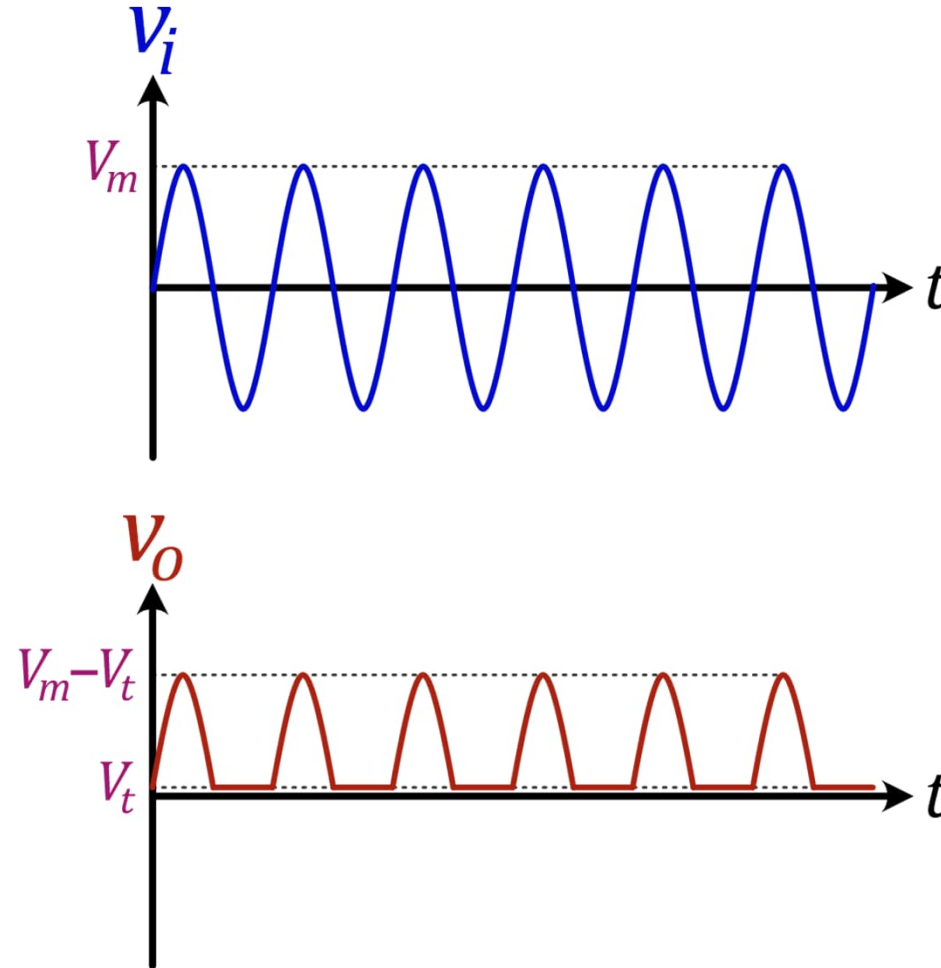
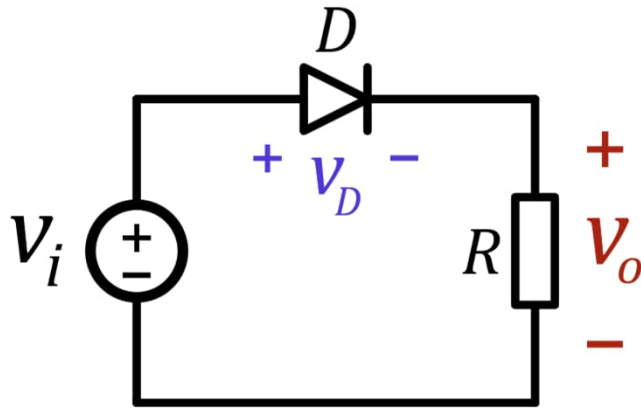


$V_0(\text{V})$	$i_R(\text{mA})$
10	9.3
5	4.3
2	1.3
0.7	0
0	0
-5	0



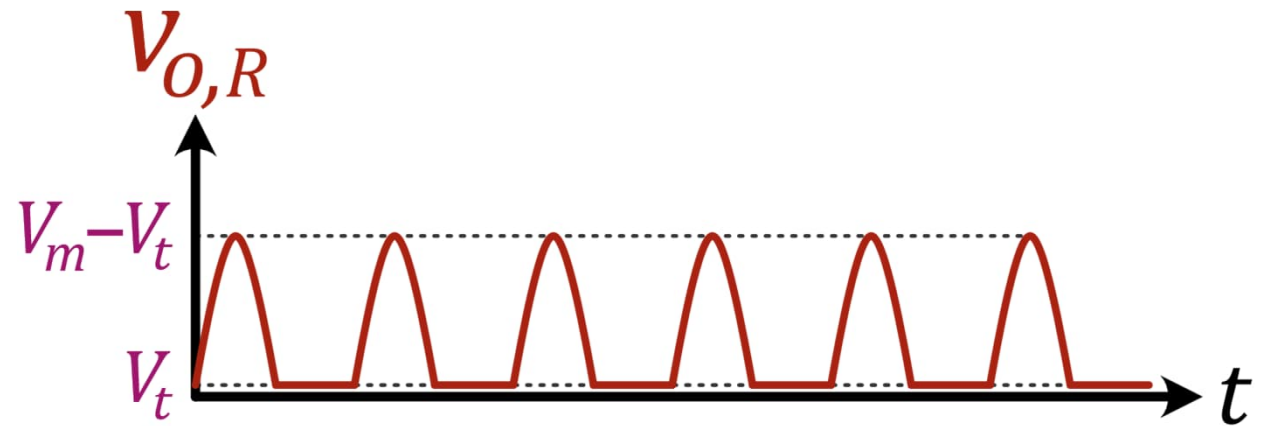
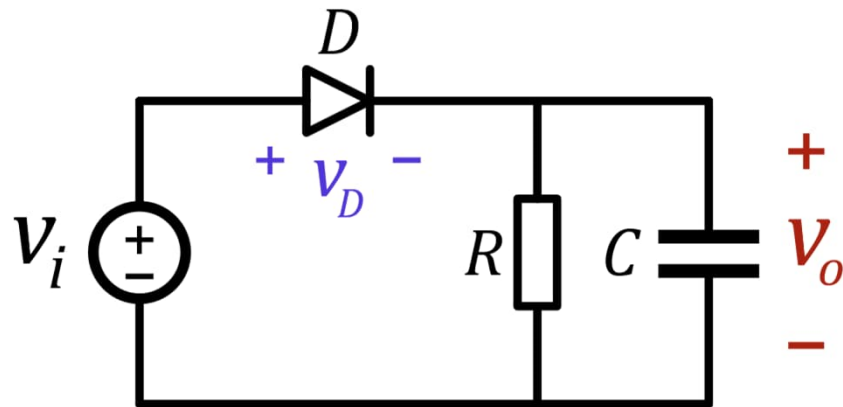
Diode Circuits – Example 3 (Rectifier)

- Draw the output voltage when feeding in a sinusoidal voltage ($V_m \gg V_t$).



Diode Circuits – Example 2 (Filtered Rectifier)

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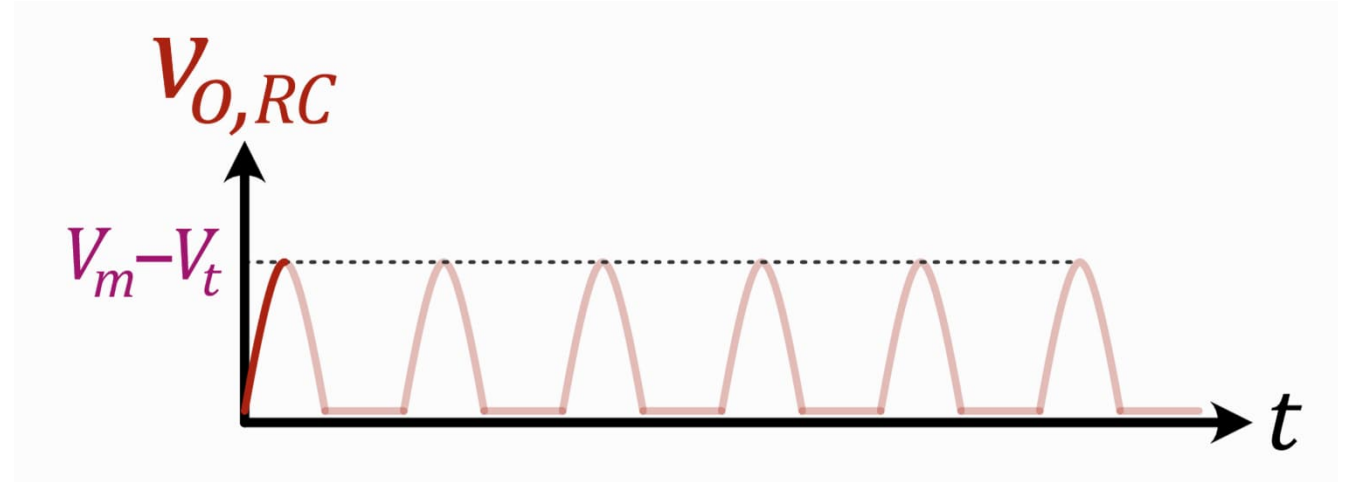
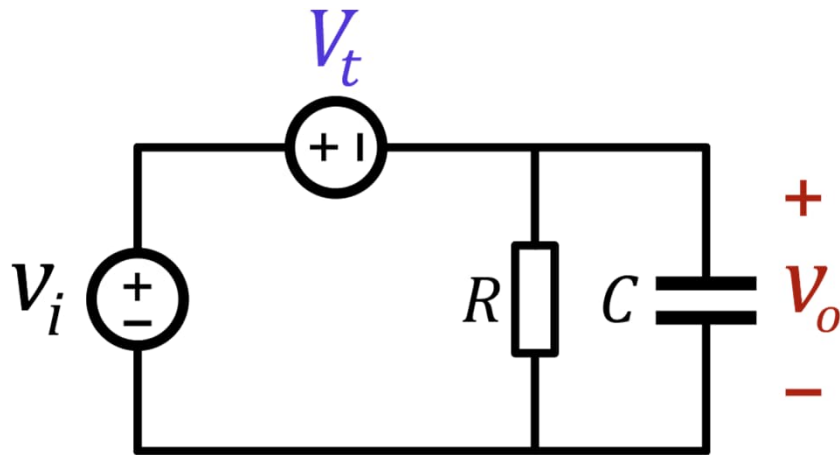


- Diode is ON if: $v_i - v_o \geq V_t$
- In the beginning: $v_o(0) = 0 \text{ V}$



Diode Circuits – Example 2 (Filtered Rectifier)

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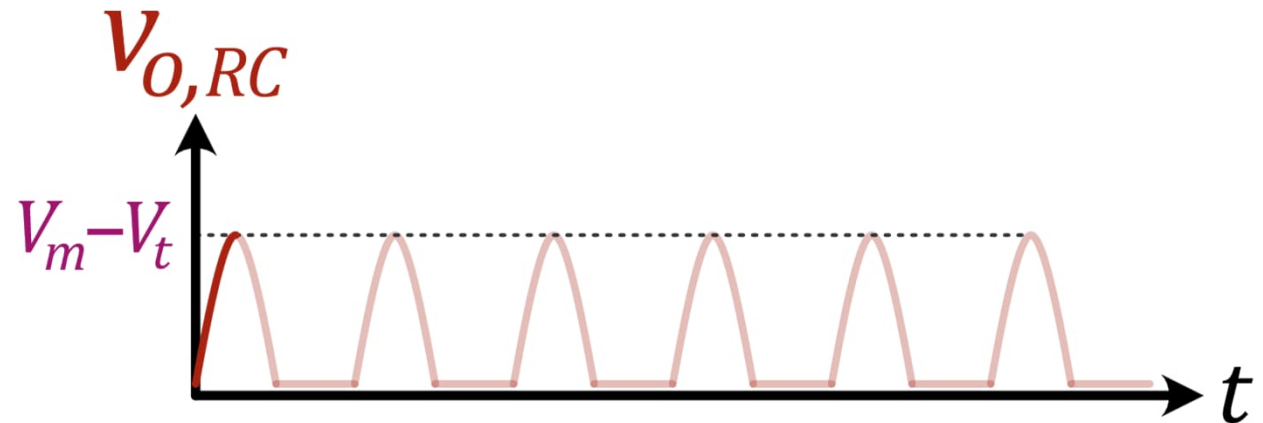
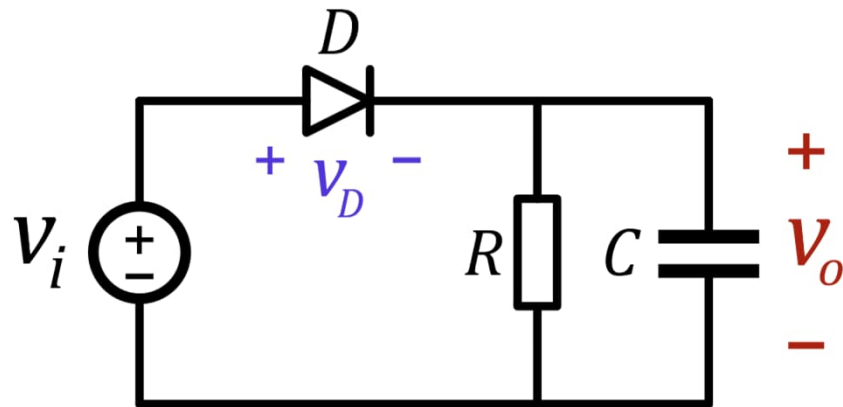


- Diode is ON if: $v_i - v_o \geq V_t$
- In the beginning: $v_o(0) = 0 \text{ V}$
- The capacitor is charged up to $V_m - V_t$
- v_o follows v_i



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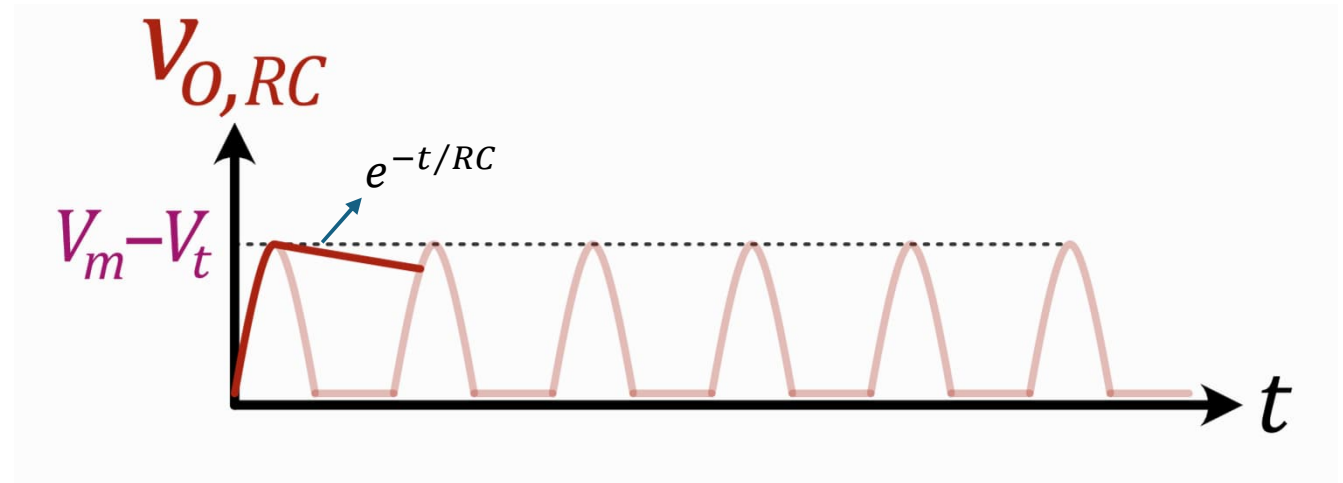
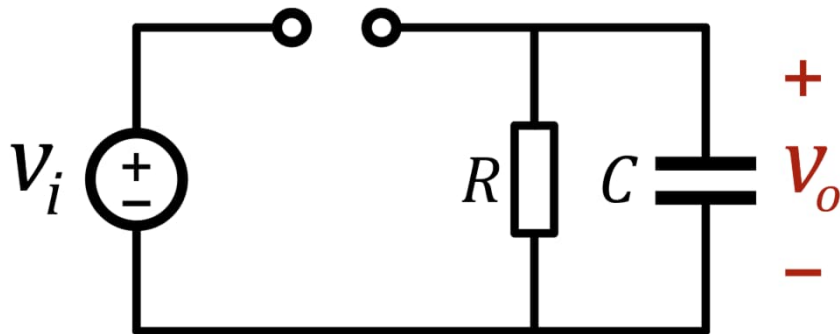


- Then v_i goes down
- $v_i < v_o \rightarrow$ Diode is turned off



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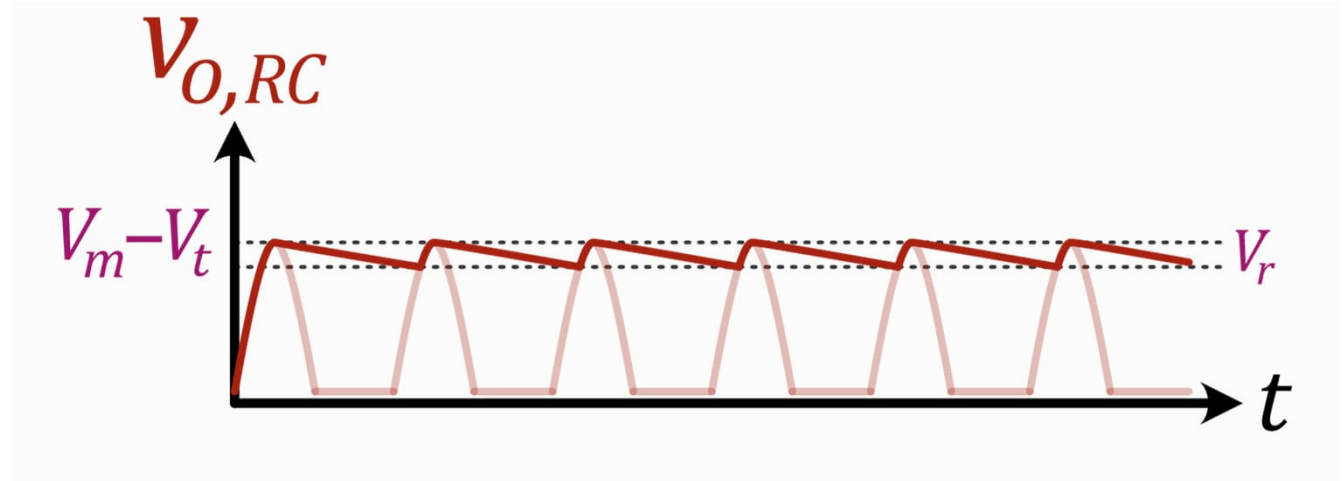
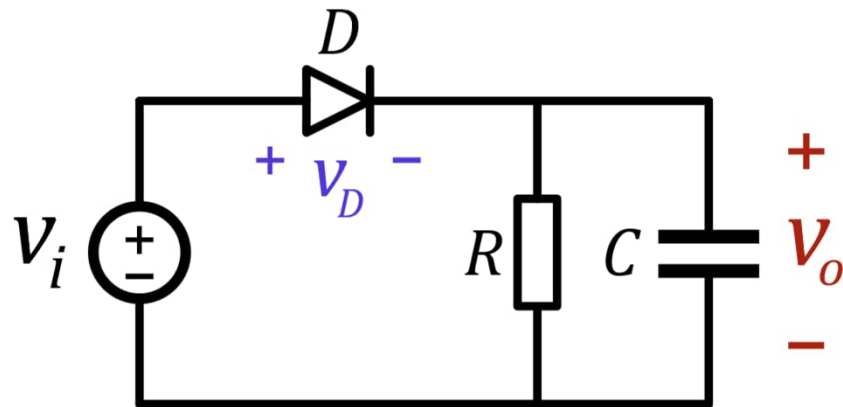


- Then v_i goes down
- $v_i < v_o \rightarrow$ Diode is turned off
- The capacitor is partially discharged by R
- v_o drops with a large time constant



Diode Circuits – Example 2 (Filtered Rectifier)

- Draw the output voltage when feeding in a sinusoidal voltage ($V_m \gg V_t$).

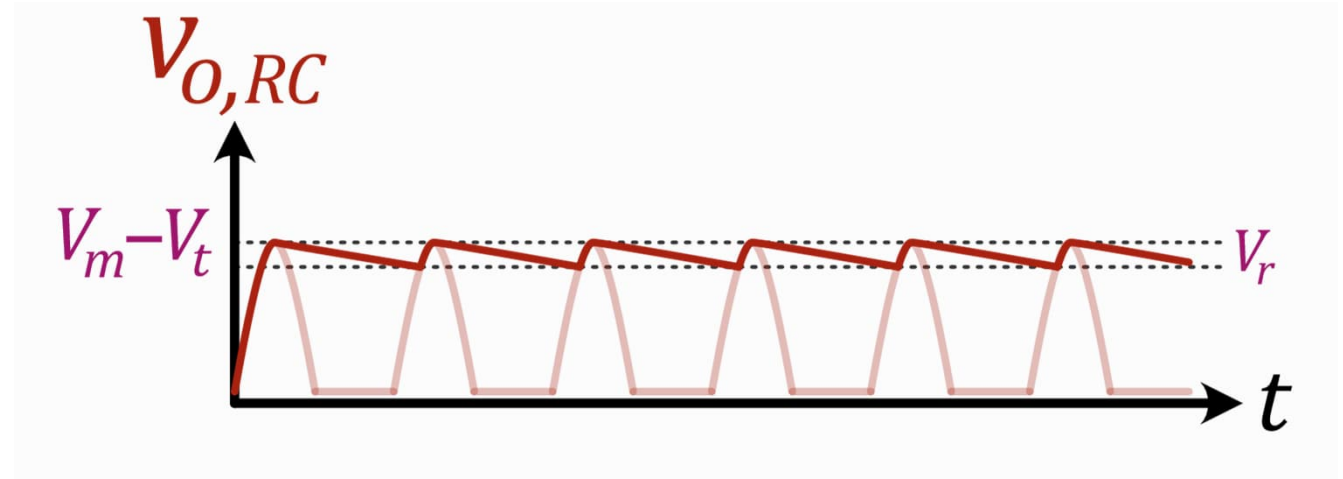
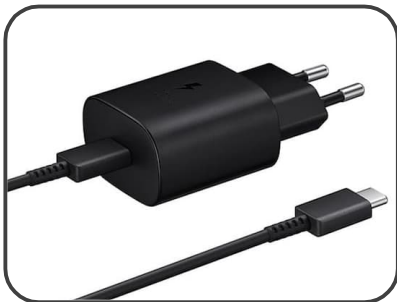
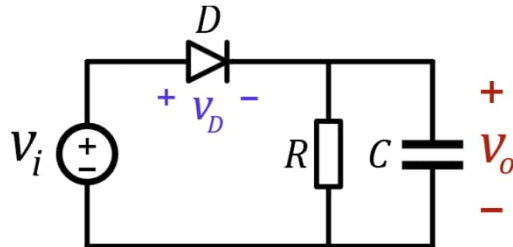


- Afterwards, the capacitor is charged and discharged repeatedly.
- A simple **AC-to-DC converter**
- Output ripple (V_r) is inversely proportional to the filter's capacitance (C).



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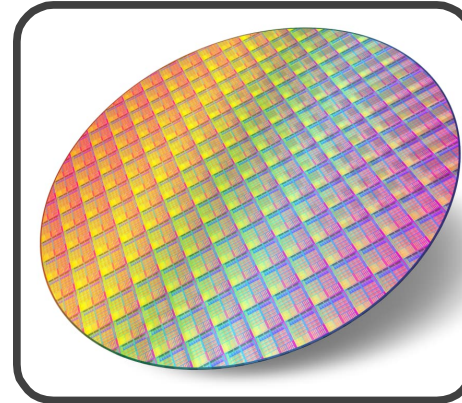


How is a Diode Fabricated?

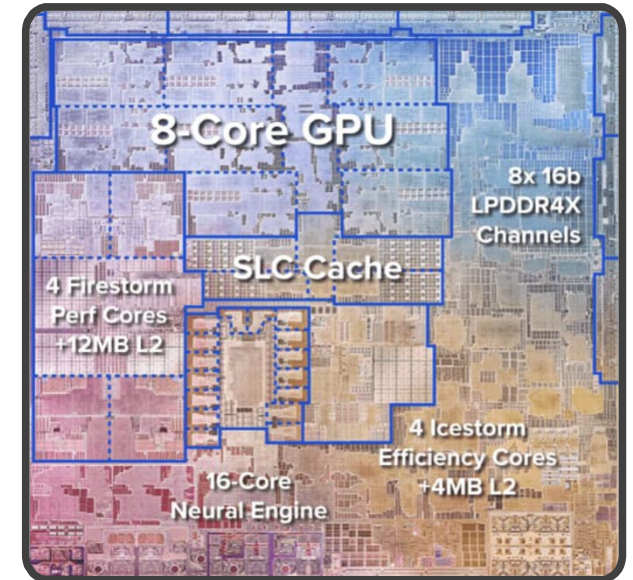
Silicon



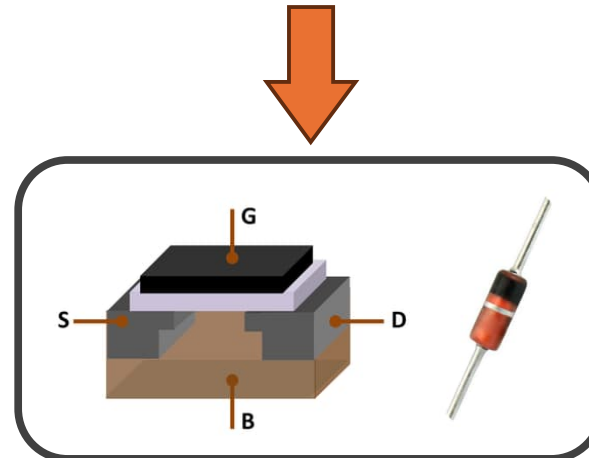
Silicon Wafer



Apple M1 CPU



Germanium



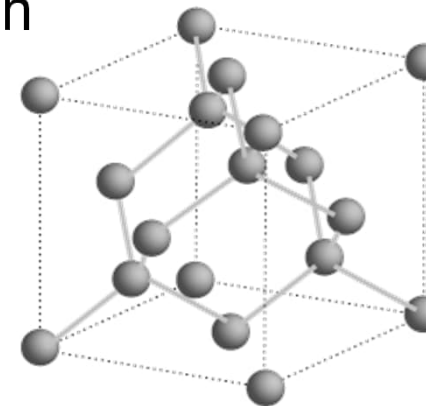
5 nm CMOS



Raw Material: Silicon

- Active devices, including diodes, are made of **semiconductors**.
- Mostly **Silicon (Si)** and **Germanium (Ge)**
- Diamond cubic crystal structure
- $\sim 5 \times 10^{22} \text{ atom/cm}^3$
- At temperature higher than 0 °K, electrons can jump from valence energy band to the conduction band.
- Therefore, the material shows lower resistance.

13	14	15	16
5 B Boron 10.81	6 C Carbon 12.01	7 N Nitrogen 14.01	8 O Oxygen 16.00
13 Al Aluminium 26.98	14 Si Silicon 28.09	15 P Phosphorus 30.97	16 S Sulfur 32.06
31 Ga Gallium 69.72	32 Ge Germanium 72.64	33 As Arsenic 74.92	34 Se Selenium 78.96
49 In Indium 114.8	50 Sn Tin 118.7	51 Sb Antimony 121.8	52 Te Tellurium 127.6



Electronic-Grade Silicon

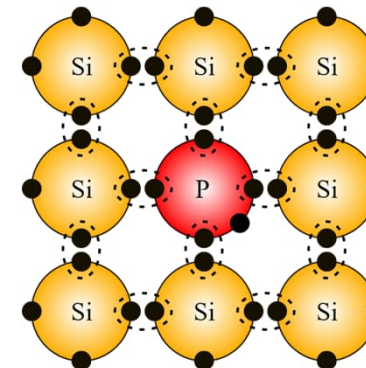
- Mechanical refinement to 98% (metallurgical grade)
- Thermo-chemical purification to **> 99.9999%**
- Controlled concentrations of impurities and dopants
- Si ingot is sliced into **wafers**
 - Diameter ~ 30 cm
 - Thickness ~ 200 to 300 μm
- Precise surface finish and dimensions



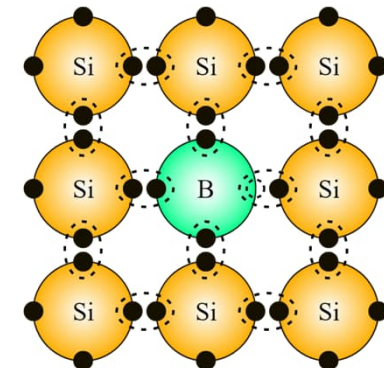
Doping and Selective Patterning

- **Dopants** (atoms from Group 13 or 15) are introduced into the silicon lattice.
- Adjust the resistivity of Si
- **Dopped Si:**
 - **N-type:** additional electrons, by implanting P or As
 - **P-type:** electron deficit, by implanting B, Al, or Ga
- **Photolithography:** selective patterning of the wafer's surface to be implanted by N/P dopants.

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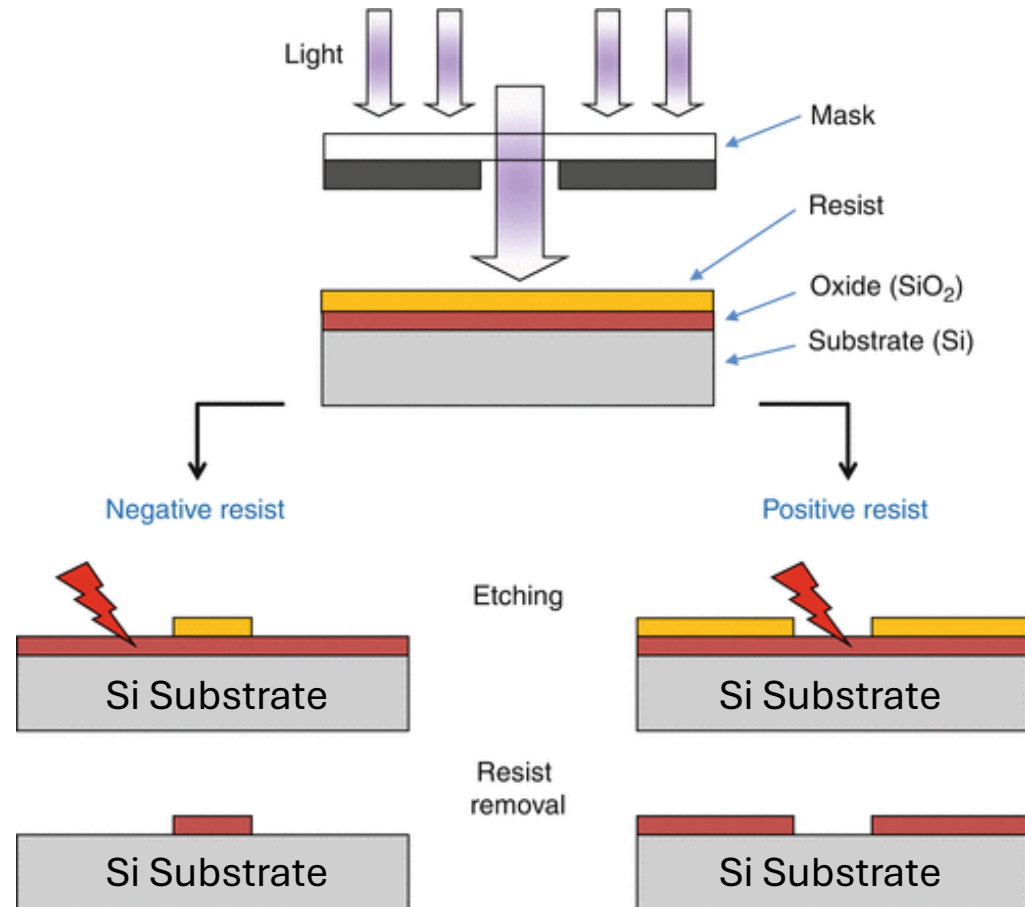
n-type



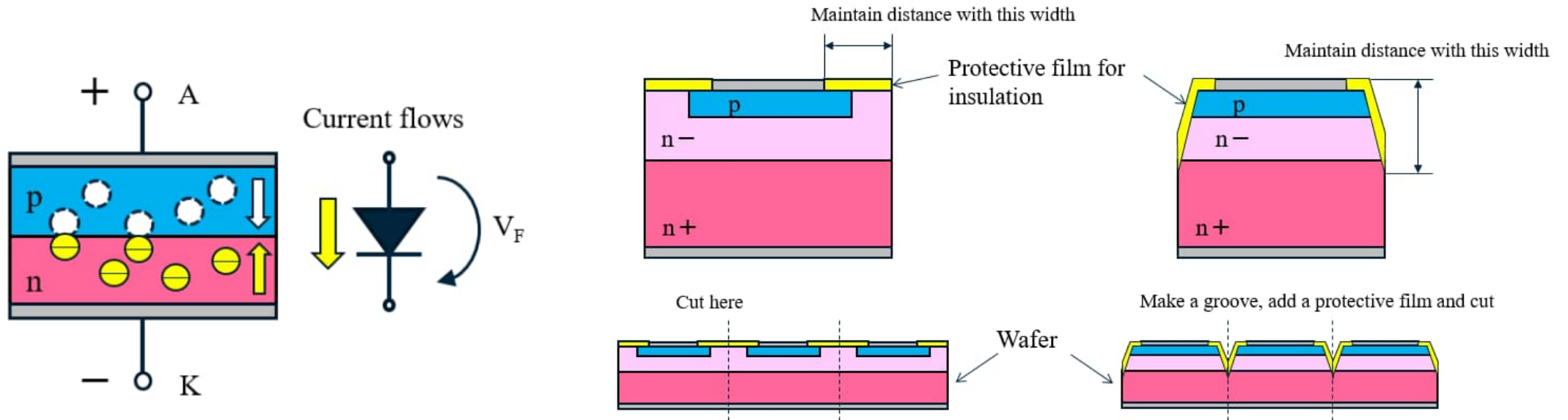
p-type



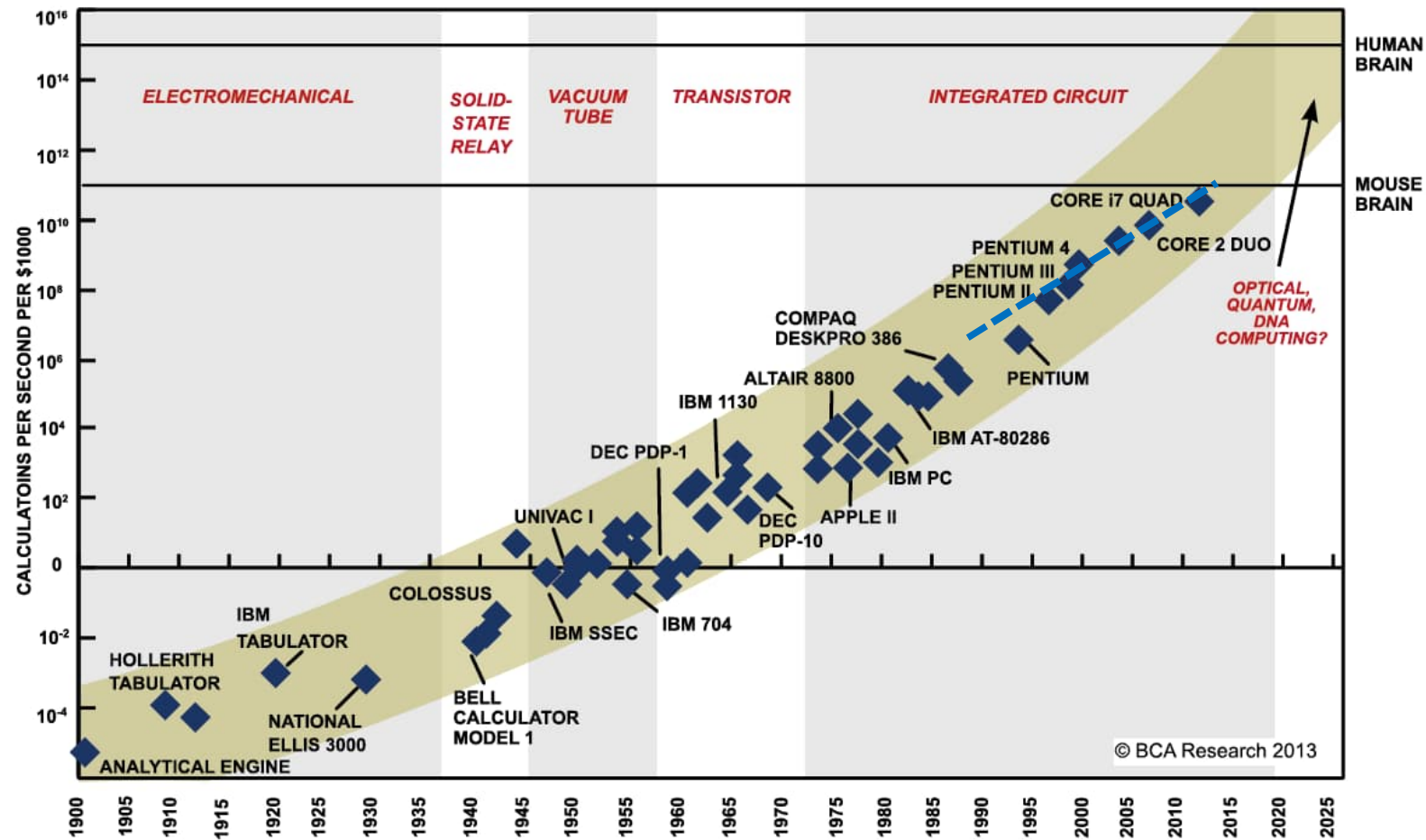
Photolithography



A diode: P-N Junction



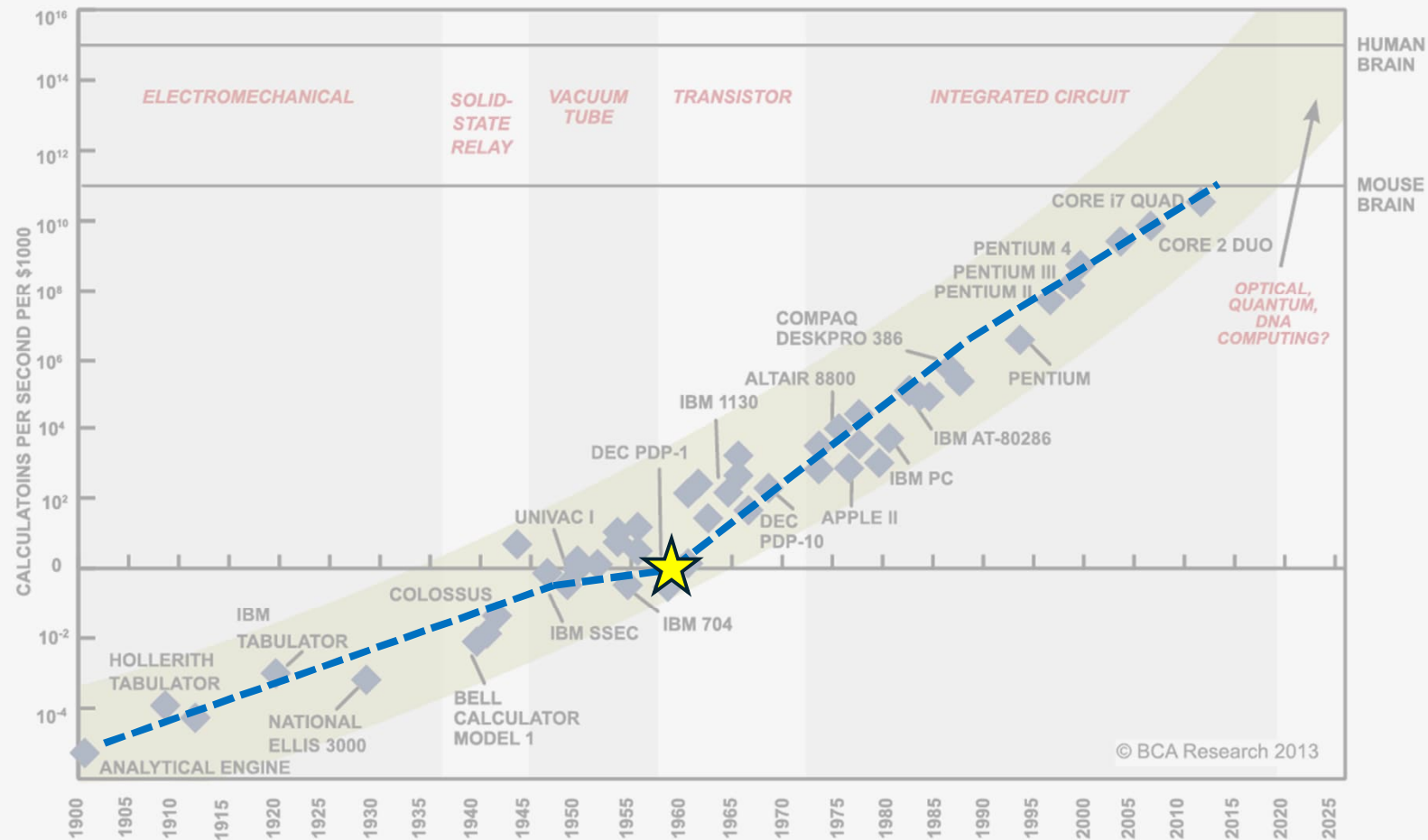
Magic of Electronic Miniaturization



SOURCE: RAY KURZWEIL, "THE SINGULARITY IS NEAR: WHEN HUMANS TRANSCEND BIOLOGY", P.67, THE VIKING PRESS, 2006. DATAPOINTS BETWEEN 2000 AND 2012 REPRESENT BCA ESTIMATES.



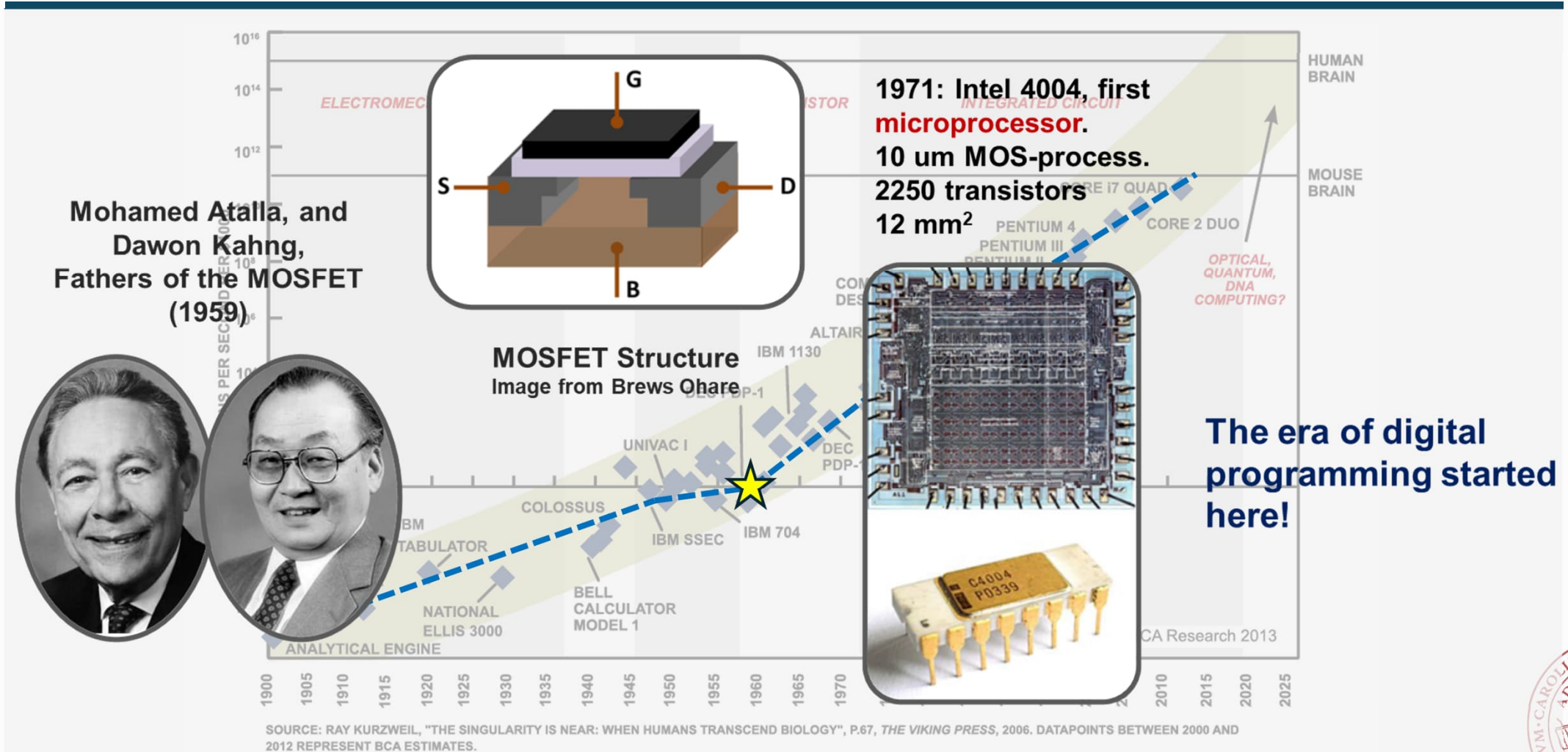
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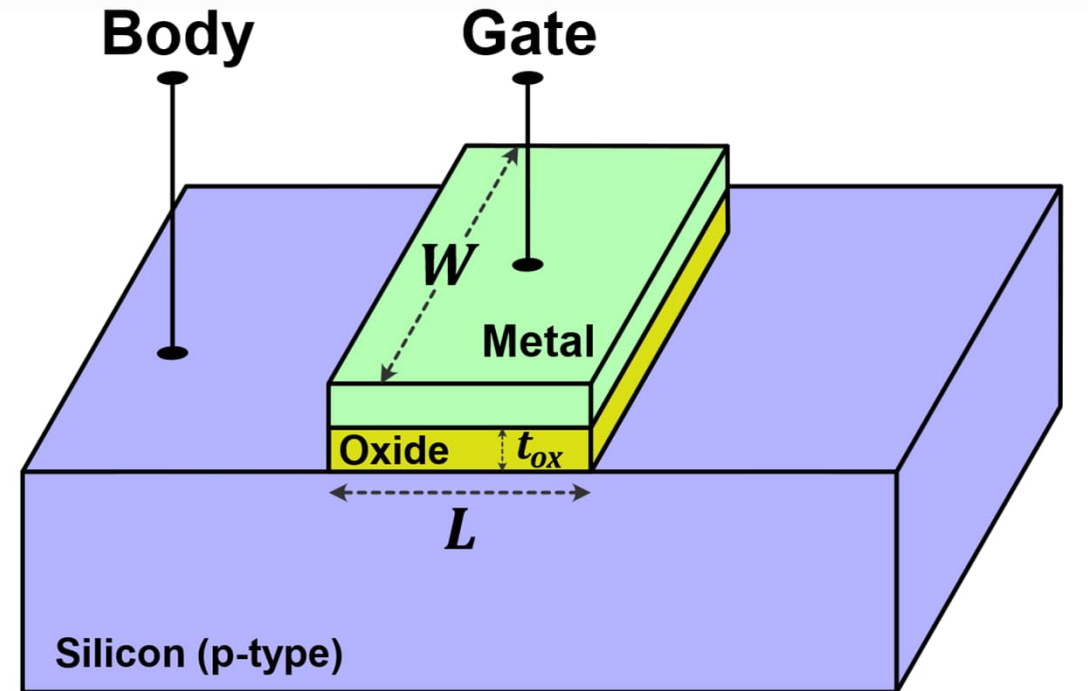


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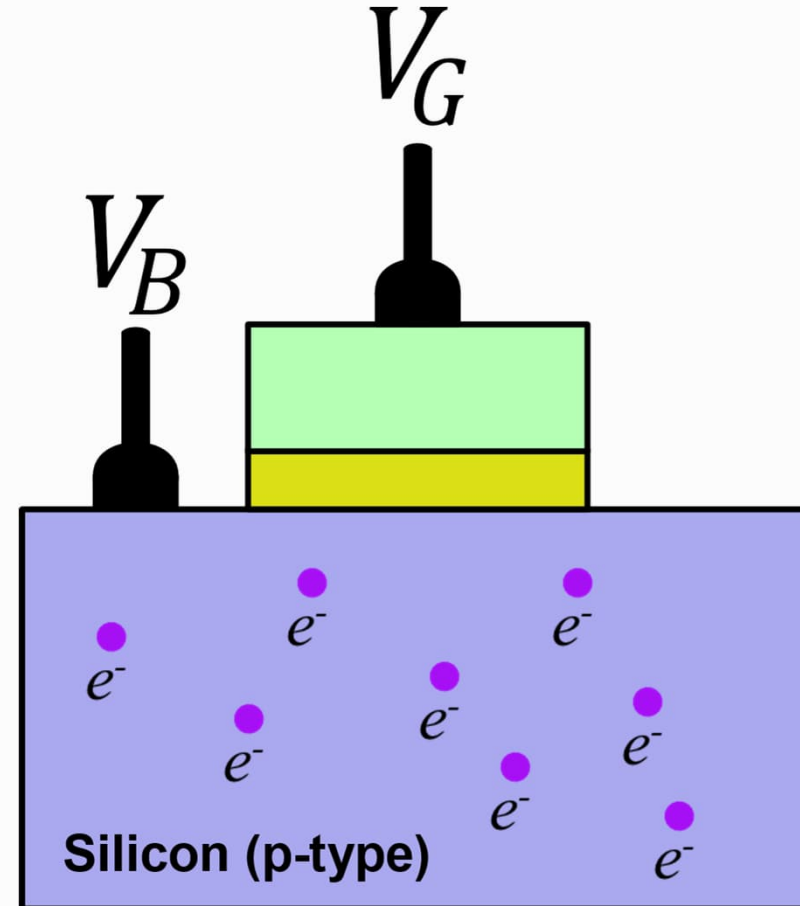
Metal-Oxide-Semiconductor (MOS) Structure

- A structure similar to a capacitor (MOSCAP)
- **Metal:** conductor, polysilicon
- **Oxide:** very thin layer (2~5 nm)
- **Silicon:** a thick layer (2~3 μm)
 - For NMOS: P-type body
 - For PMOS: N-type body



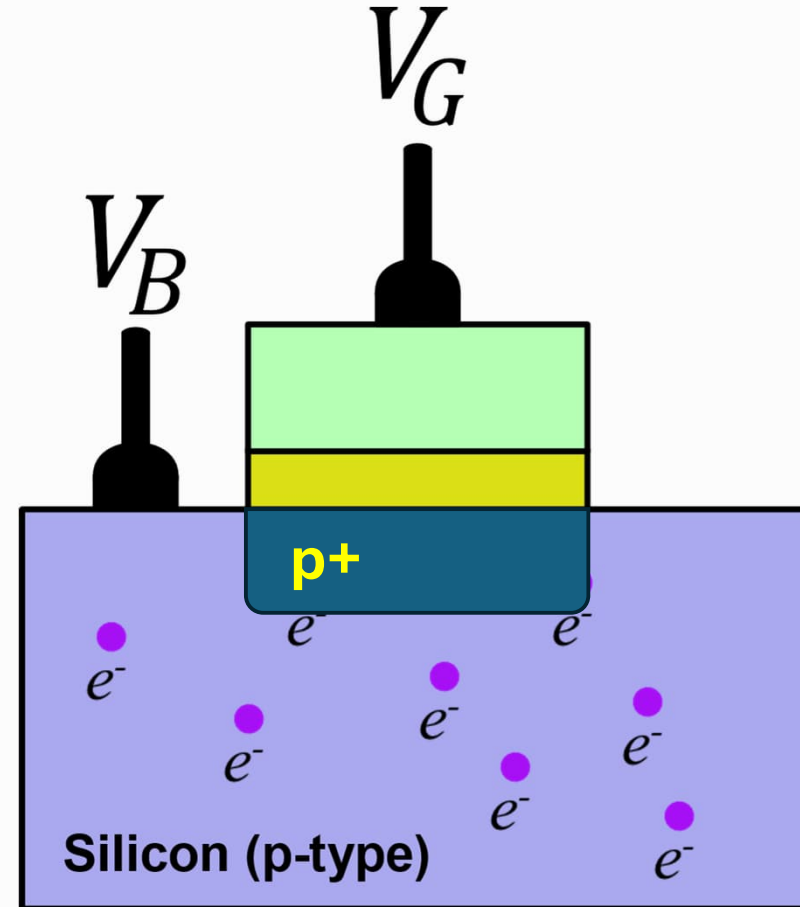
Metal-Oxide-Semiconductor (MOS) Structure

- Two terminals: **Gate** and **Body**
- Body is normally connected to GND ($V_B = 0$)
- Gate voltage (V_G) controls the **local concentration of electrons** underneath the oxide-silicon interface.



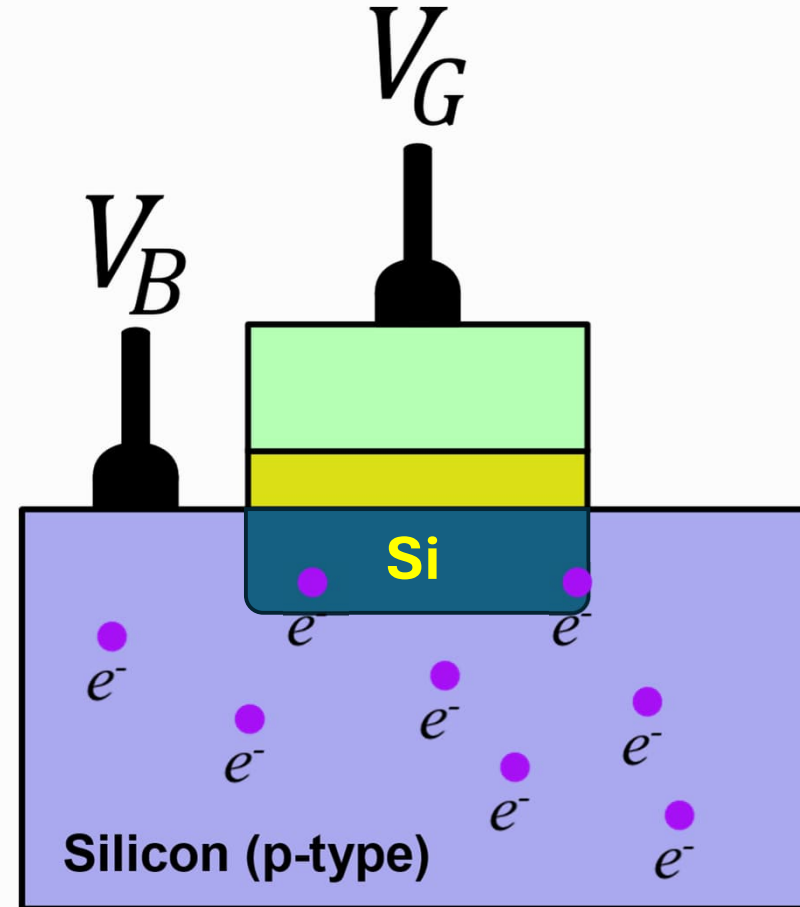
Accumulation

- $V_B = 0$
- $V_G < 0$
- More deficit of electrons underneath the gate oxide
- Silicon become more p-type (p+)



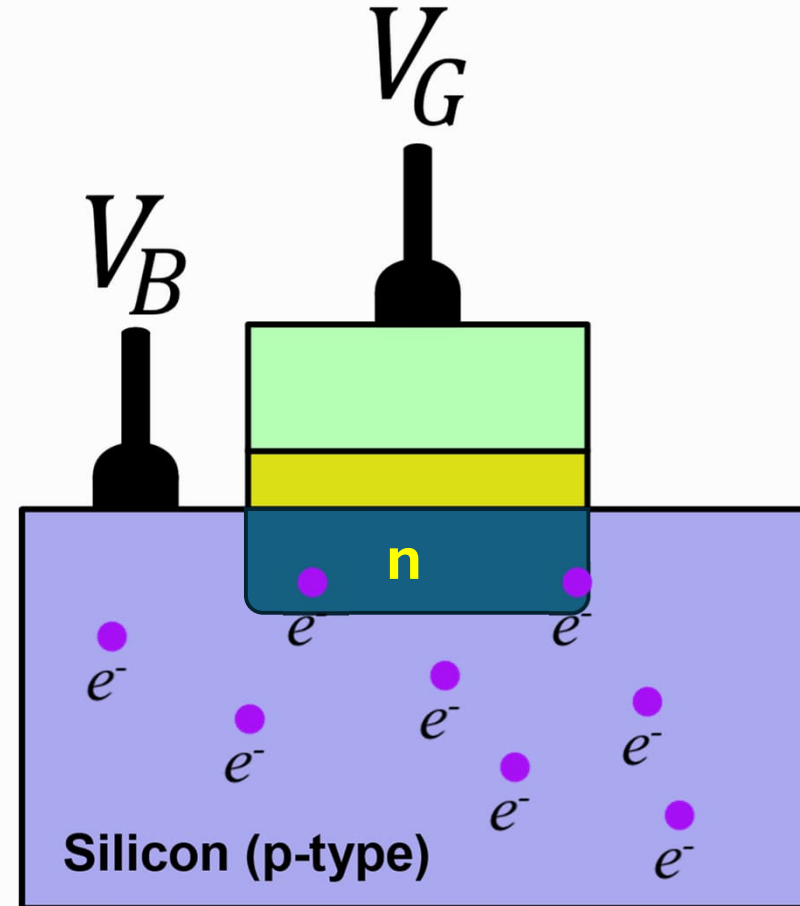
Depletion

- $V_B = 0$
- $0 < V_G < V_t$
- Less deficit of electrons underneath the gate oxide
- Not enough to make it N-type
- Behaves like undoped silicon



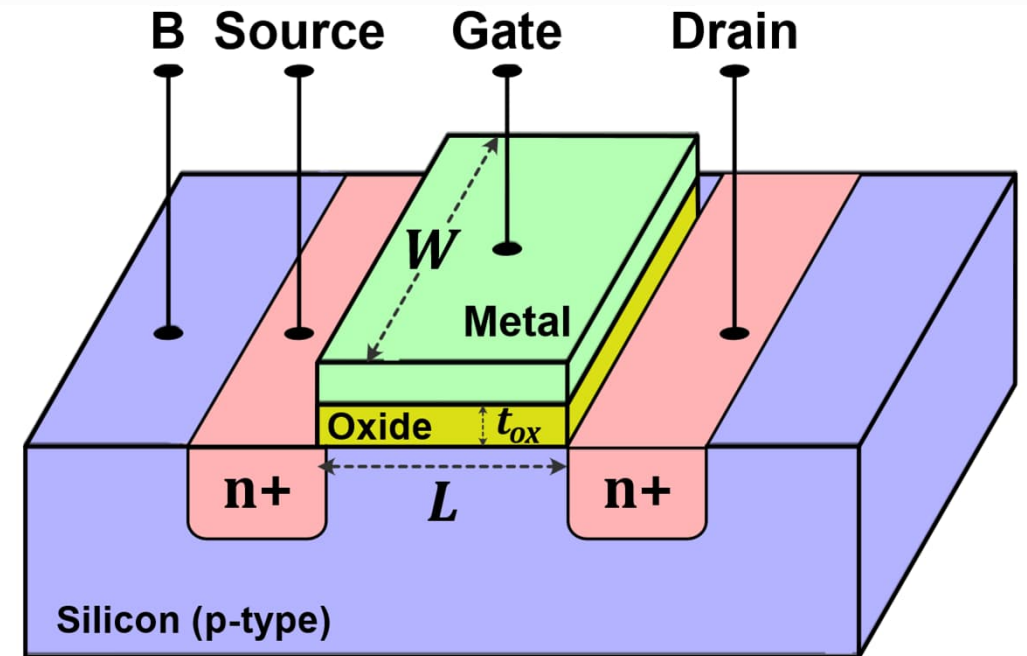
Inversion

- $V_B = 0$
- $V_t < V_G$
- **Excess** electrons underneath the gate oxide
- Locally N-type Si, a thin layer within the body (channel)



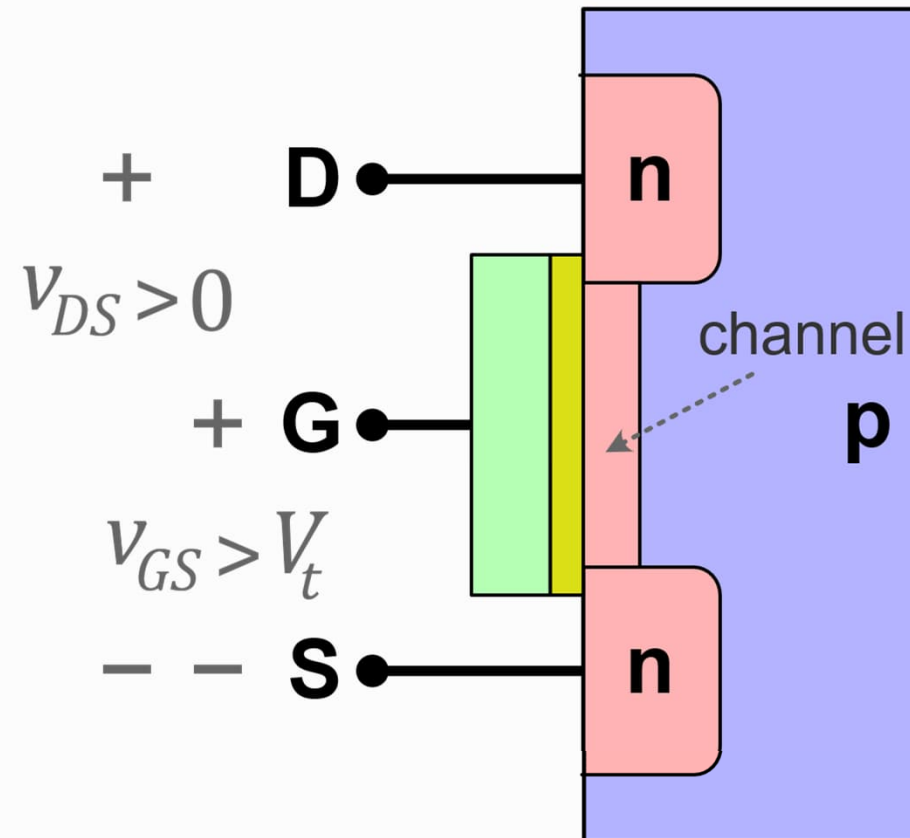
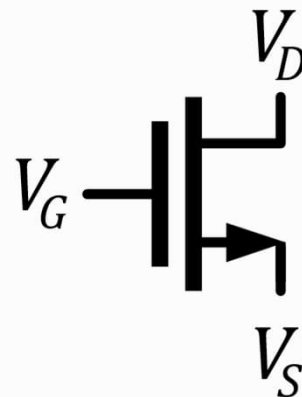
MOS Field-Effect Transistor (MOSFET)

- We created a voltage-controlled material
- The resistivity of the channel is controlled by $V_G \rightarrow$ variable resistance (R_{ds})
- By implanting two n-type regions on the sides of the channel (with some overlap with the gate), a switch is constructed.
- **Source (S)** and **Drain (D)** terminals.



MOS Field-Effect Transistor (MOSFET)

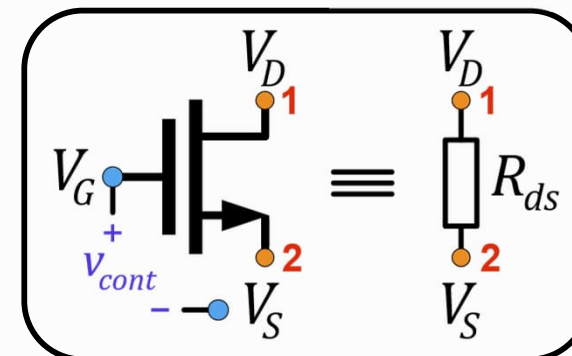
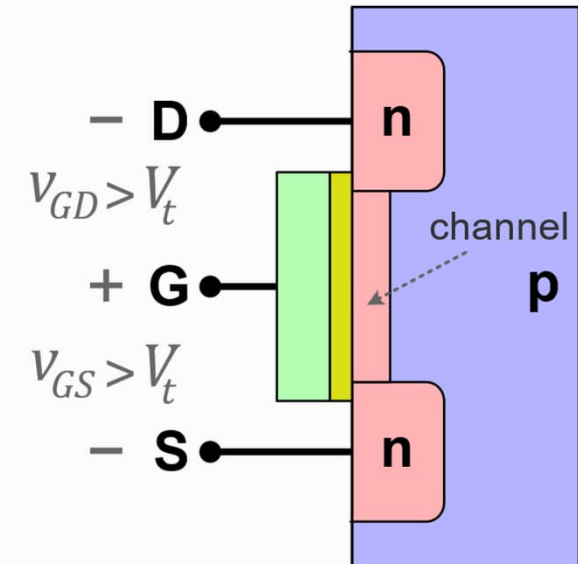
- When $v_{GS} > V_t$ channel is formed next to the source.
- When $v_{DS} > 0$, electrons can flow from S to D through the channel.
- Schematic symbol of NMOS



MOSFET as a Switch (Deep-Triode Region)

- $v_{GS} > V_t \rightarrow$ Channel formation
- $v_{DS} \approx 0 \rightarrow$ Uniform channel
- Switch's performance depends on:
 - Material properties: $K_n \triangleq \frac{1}{2} \left(\frac{W}{L} \right) \mu_n C_{ox}$
 - Electron mobility: μ_n
 - Gate-oxide capacitance per area: $C_{ox} \triangleq \frac{\epsilon_{ox}}{t_{ox}}$
 - Overdrive voltage: $v_{ov} \triangleq v_{GS} - V_t$

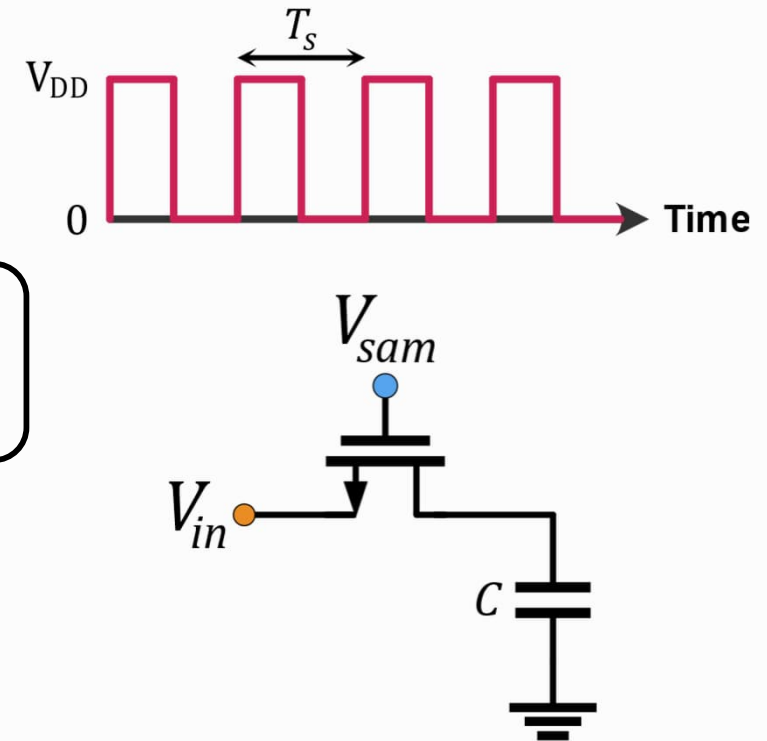
$$R_{ds} = \frac{1}{2K_n v_{ov}}$$



Pause and Ponder 1

- Derive an expression for the maximum achievable sampling frequency in an N-bit ADC.

$$\left\{ \begin{array}{l} R_{ds} = \frac{1}{2K_n v_{ov}} \\ \tau = R_{ds} C \\ f_{s,max} = \frac{1}{2N(\ln 2)\tau} \end{array} \right. \Rightarrow f_{s,max} = \frac{K_n v_{ov}}{N(\ln 2)C}$$



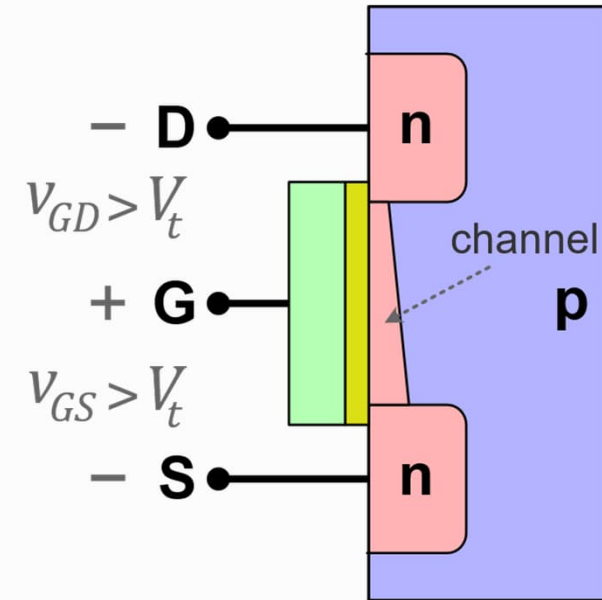
- By halving the channel length (L), how does the maximum sampling frequency increase?

$$f_{s,max} = \frac{\mu_n}{N(\ln 2)} \cdot \frac{C_{ox}}{C} \cdot \frac{W}{L} v_{ov} \Rightarrow \text{It is doubled. Really?!}$$



Linear (Triode) Region of Operation

- $v_{GS} > V_t \rightarrow$ Channel formation
- $0 < v_{DS} < (v_{GS} - V_t) \rightarrow$ Non-uniform channel
- The transistor is symmetrical
 - No physical difference between S and D
- Increasing $v_{DS} \rightarrow$ Lowering $v_{GD} = v_{GB}$ (at D)
- Lower Inversion at D \rightarrow Higher channel resistance \rightarrow Lower current

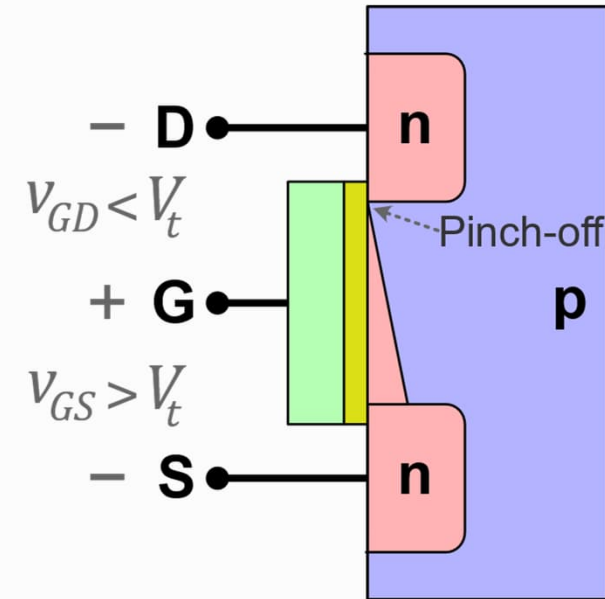


$$i_D = K_n(2v_{ov}v_{DS} - v_{DS}^2)$$



Saturation Region

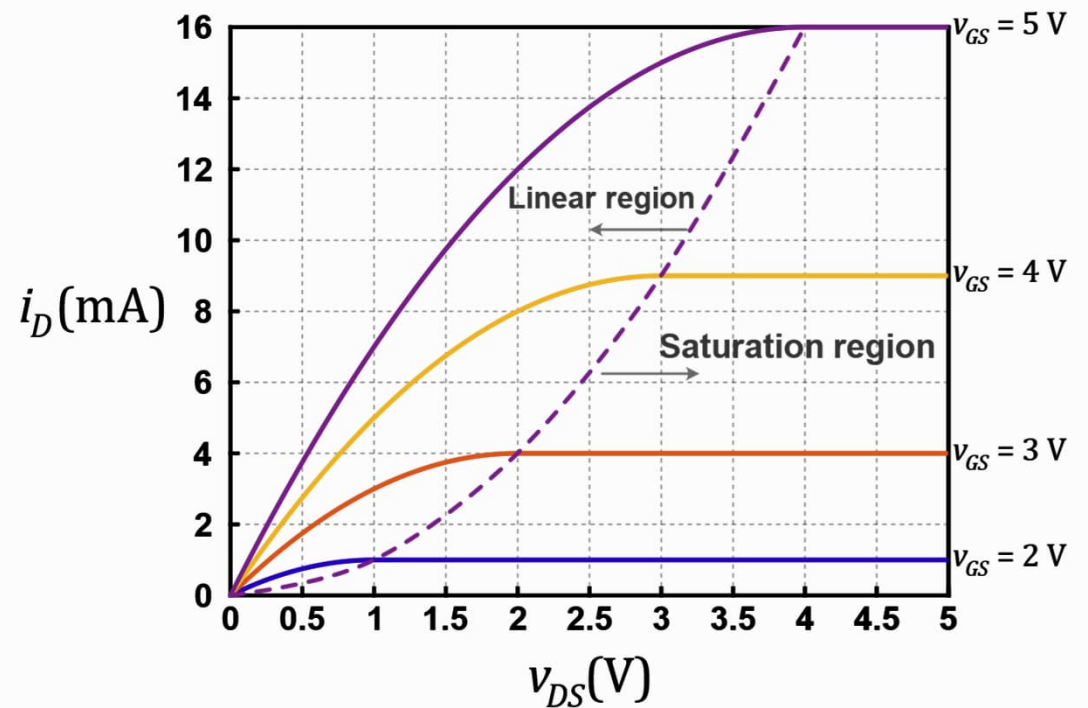
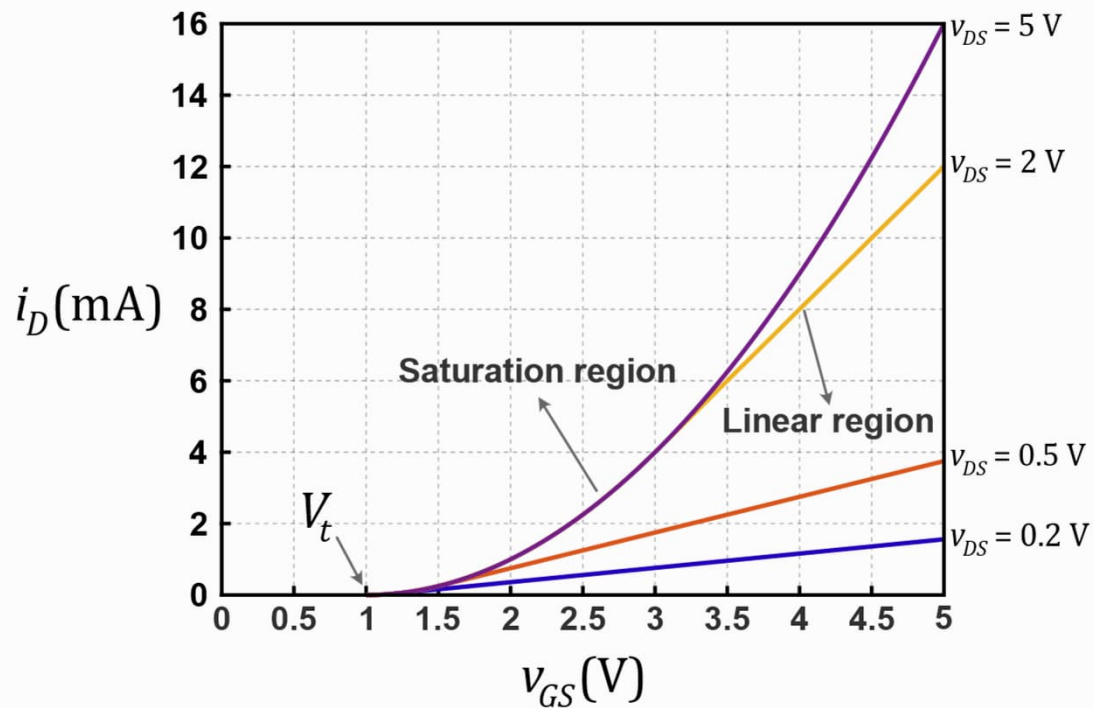
- $v_{GS} > V_t \rightarrow$ Channel formation
- $(v_{GS} - V_t) < v_{DS} \rightarrow$ **Pinched-off** channel
- The channel width is reduced to zero at D
- Increasing $v_{DS} \rightarrow$ Ideally, no effect on i_D anymore!
- Suitable operating region for **analog amplification**



$$i_D = K_n v_{ov}^2$$

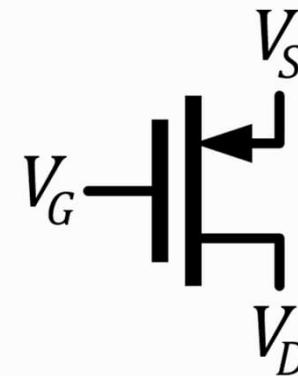
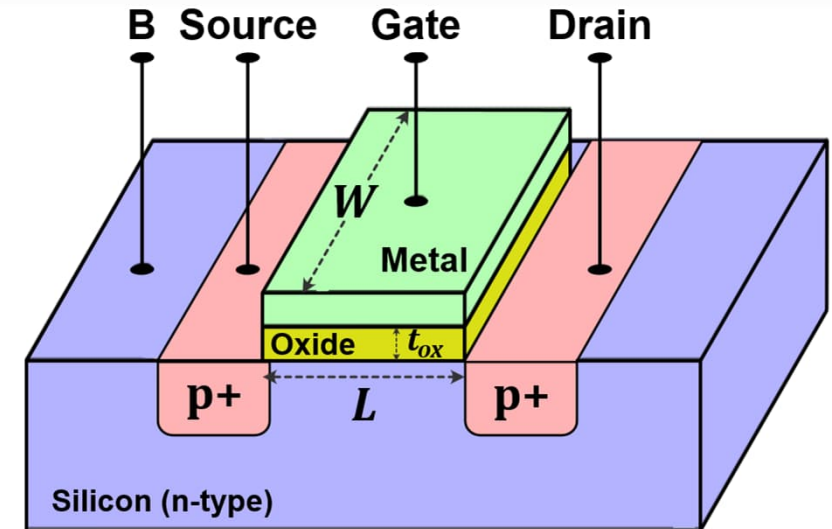


$i - v$ Characteristics of an NMOS Transistor



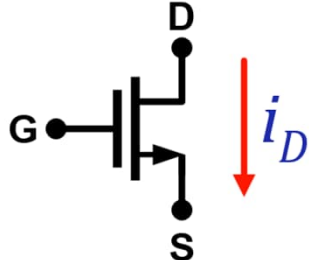
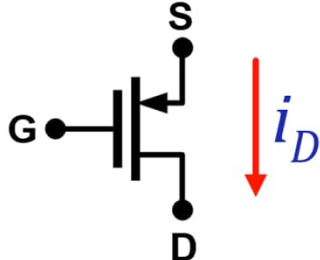
PMOS: MOS in N-Type Substrate

- When $v_{GS} < V_t < 0$, a low-resistance p-type channel is formed.
- A negative v_{DS} create a current (i_D) flowing from S to D.
- The same equations describe i_D as a function of v_{GS} and v_{DS} .



Complementary MOS (CMOS) Technology

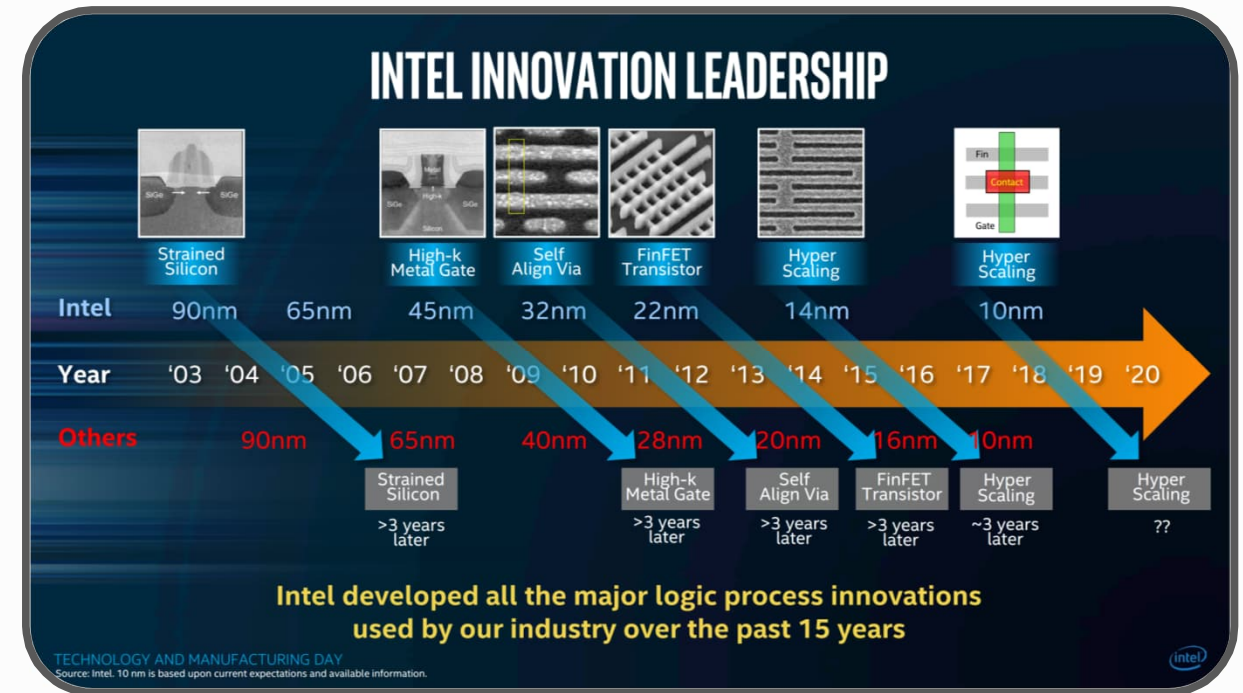
- Both NMOS and PMOS devices are integrated on the same chip.
- NMOS switch is activated by logical 1 ($0 < V_t < v_{GS}$).
- PMOS switch is activated by logical 0 ($v_{GS} < V_t < 0$).

	NMOS	PMOS
Kretssymbol		
$\mu \approx$	$675 \text{ cm}^2 \text{V}^{-1} \text{s}^{-1}$	$240 \text{ cm}^2 \text{V}^{-1} \text{s}^{-1}$
$\kappa \approx$	$115 \mu \text{AV}^{-2}$	$40 \mu \text{AV}^{-2}$
$V_t \approx$	$+0.5 \text{ V}$	-0.6 V
Subtröskel (strykt område)	$v_{GS} \leq V_t,$ $v_{DS} \geq 0,$ $i_D = 0$	$v_{GS} \geq V_t,$ $v_{DS} \leq 0,$ $i_D = 0$
Linjärt område	$v_{GS} \geq V_t,$ $0 \leq v_{DS} \leq v_{GS} - V_t,$ $i_D = K(2(v_{GS} - V_t)v_{DS} - v_{DS}^2)$	$v_{GS} \leq V_t,$ $0 \geq v_{DS} \geq v_{GS} - V_t,$ $i_D = K(2(v_{GS} - V_t)v_{DS} - v_{DS}^2)$
Mättnads- område	$v_{GS} \geq V_t,$ $v_{DS} \geq v_{GS} - V_t,$ $i_D = K(v_{GS} - V_t)^2$	$v_{GS} \leq V_t,$ $v_{DS} \leq v_{GS} - V_t,$ $i_D = K(v_{GS} - V_t)^2$
v_{DS}, v_{GS}	Vanligtvis positiva	Vanligtvis negativa



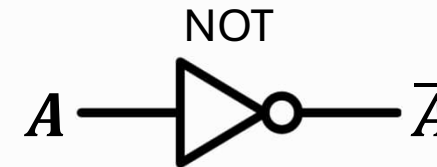
CMOS Process Nodes

- **Feature size:** Represents the minimum gate length (L_{min}) achievable in a given CMOS technology generation.
- **Process Node:** Identified by the feature size
- Steady **miniaturization** over decades
- Approaching quantum physics (atomic-scale) limits

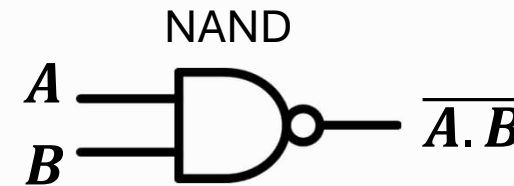


Digital Logic Operators and Gates

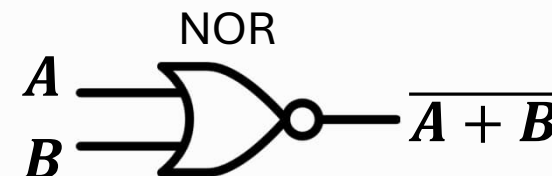
- Boolean logic condition: **True** and **False**
- In binary digital systems:
 - **Logical "1"** = True, corresponds to high voltage level (close enough to **the supply voltage, V_{DD}**)
 - **Logical "0"** = False, corresponds to low voltage level (close enough to **the GND voltage, 0 V**)
- Fundamental digital logic operators and gates:
 - **NOT, NAND, NOR**
 - **Digital gate:** electronic implementation of an operator



A	\bar{A}
0	1
1	0



A	B	$\overline{A \cdot B}$
0	0	1
0	1	1
1	0	1
1	1	0

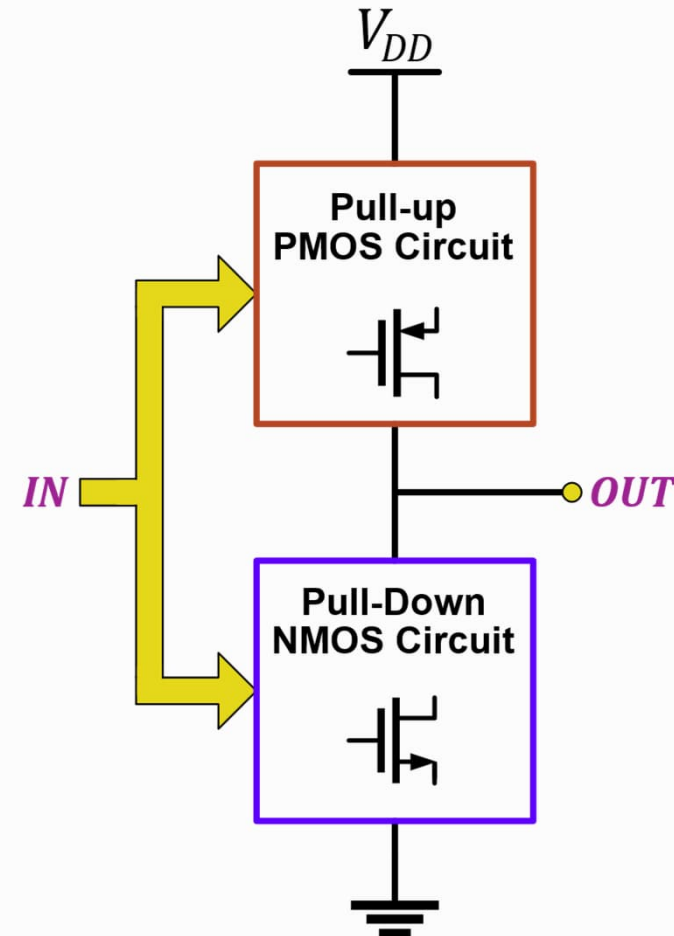


A	B	$\overline{A + B}$
0	0	1
0	1	0
1	0	0
1	1	0



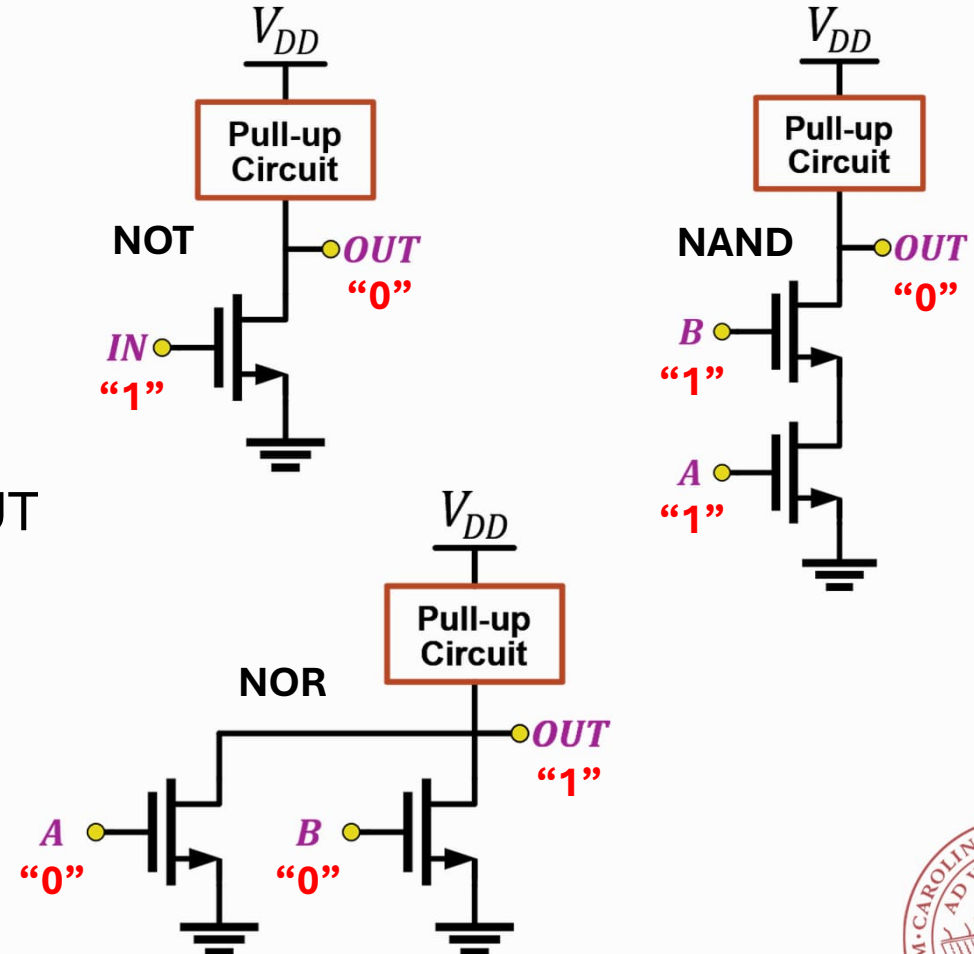
CMOS Logic Gates

- A gate decides to connect the output node to either GND or V_{DD} according to its digital input state (“0” or “1”) and the truth table.
- Lower-half (Pull-down) circuit connects to GND
- Upper-half (Pull-up) circuit connects to VDD
- CMOS construction:
 - **Pull-down:** NMOS
 - **Pull-up:** PMOS



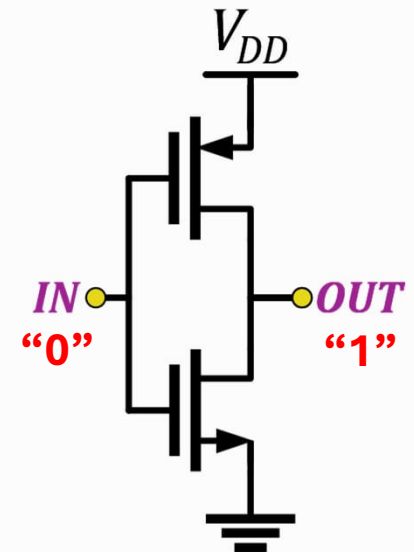
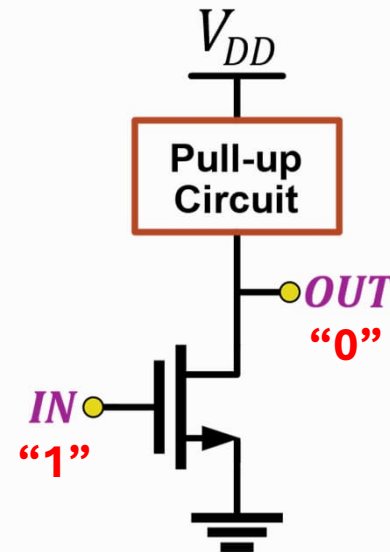
CMOS Logic Gates, Pull-Down

- Start from the lower half
- NMOS switch conducts when its input is “1”
- However, when an NMOS between GND and OUT is ON, the output becomes “0”; therefore:
- **Inverting:** NMOS switch between GND and OUT
- **NAND-ing:** **Series** NMOS switches
- **NOR-ing:** **Parallel** NMOS switches



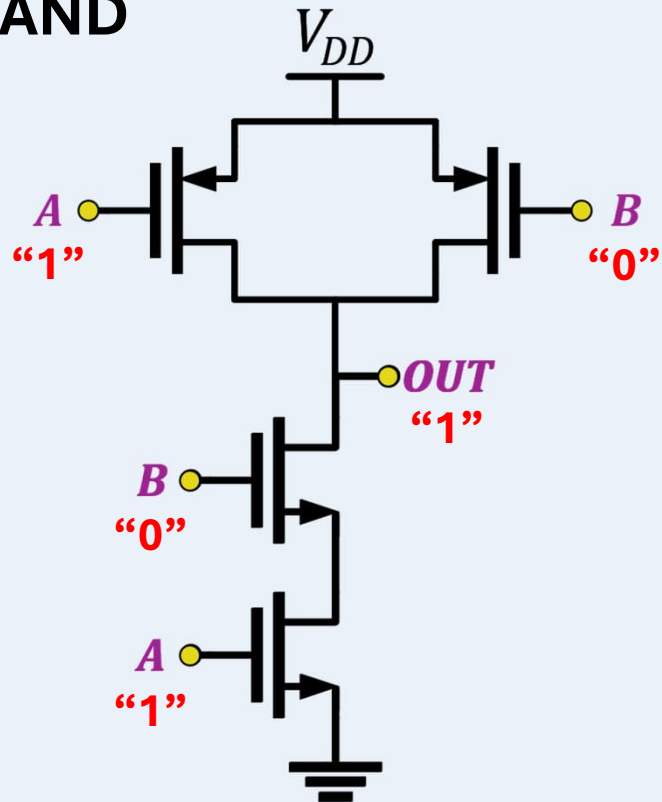
CMOS Logic Gates, Pull-Up

- The upper half complements the lower half.
- **Reminder:** PMOS conducts when it receives a “0” digital input
- **Duality:**
 - Series NMOS \equiv Parallel PMOS
 - Parallel NMOS \equiv Series PMOS

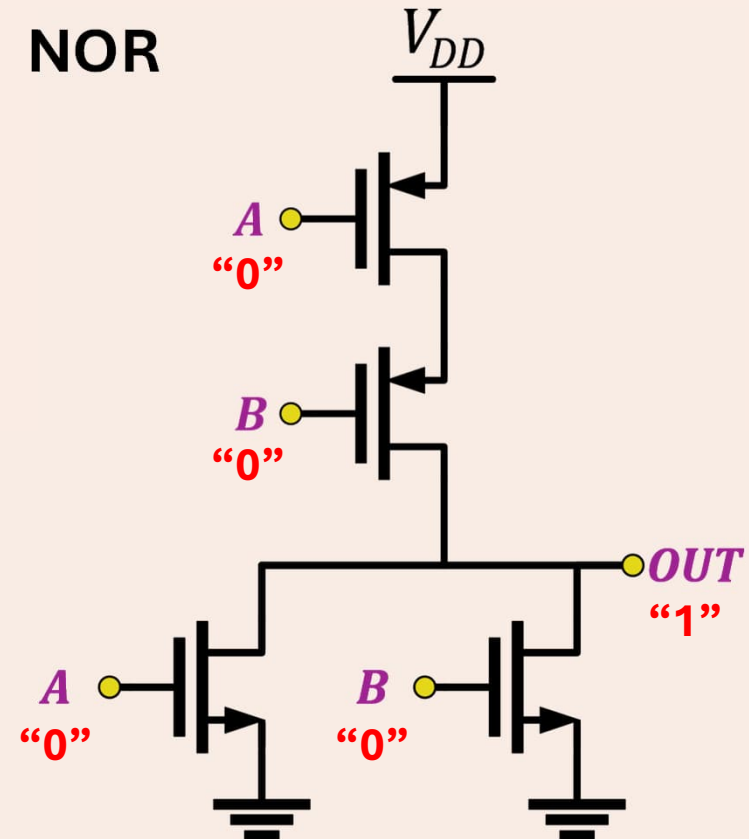


CMOS NAND and NOR

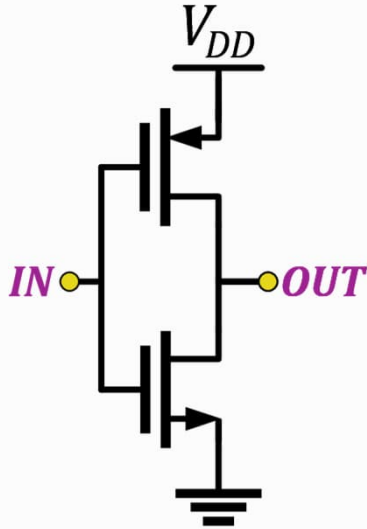
NAND



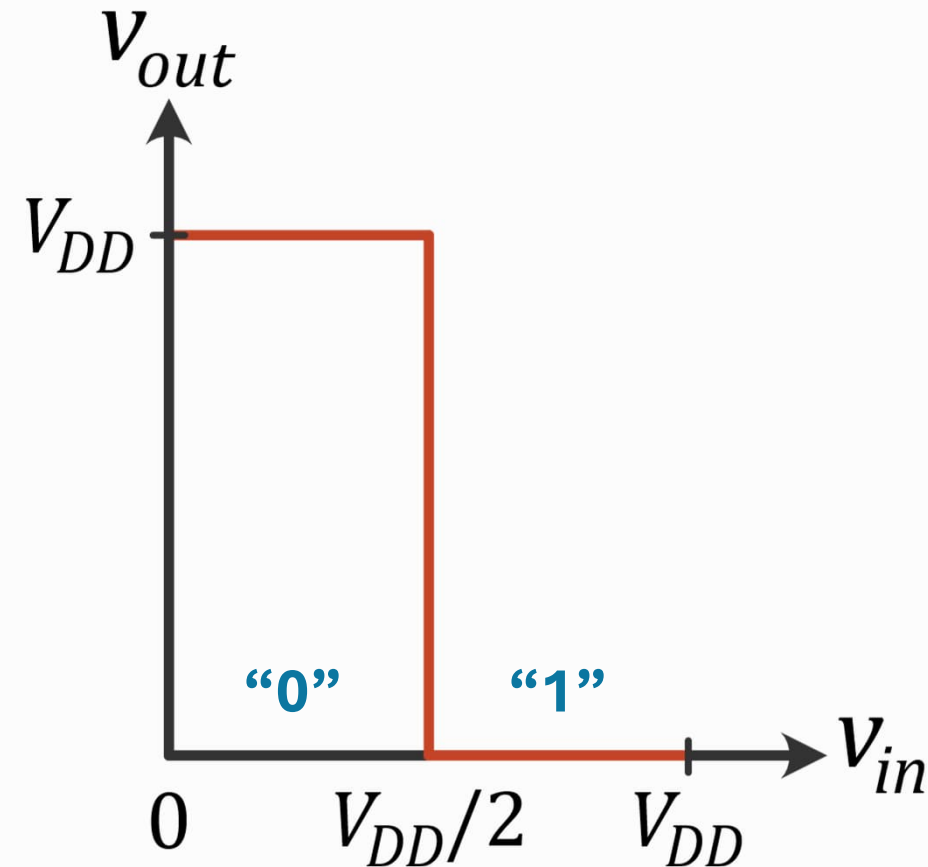
NOR



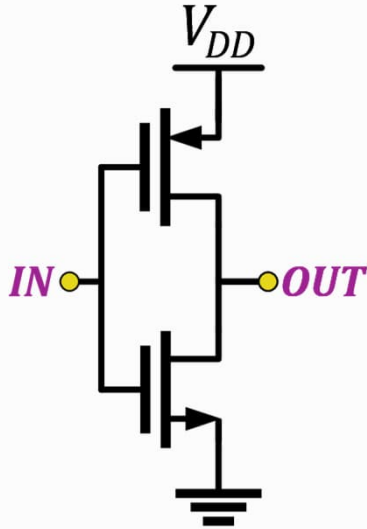
Voltage Transfer Characteristics



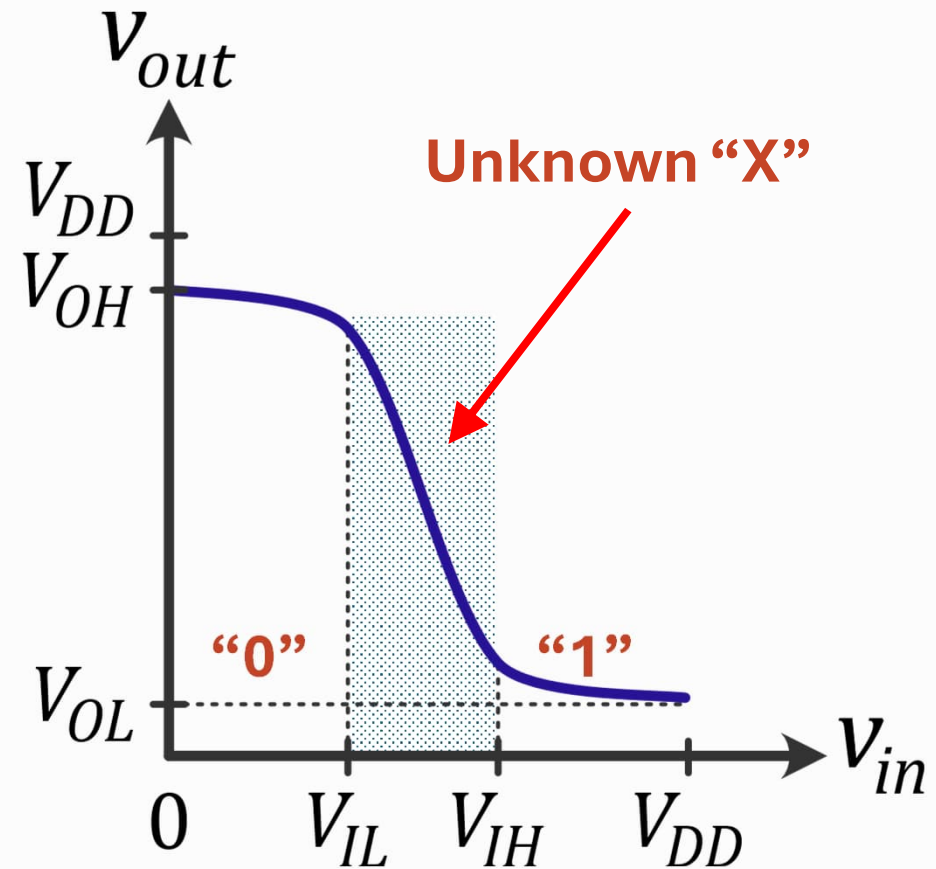
- **Ideal** input-output characteristics
- Low State: "0" $\equiv [0, V_{DD}/2)$
- High State: "1" $\equiv (V_{DD}/2, V_{DD}]$



Voltage Transfer Characteristics

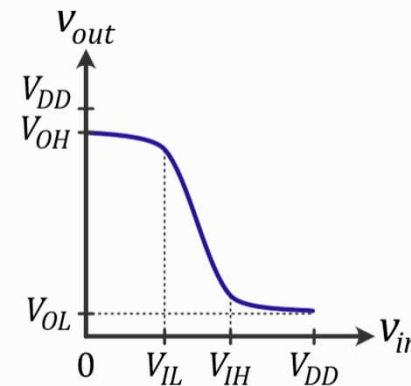
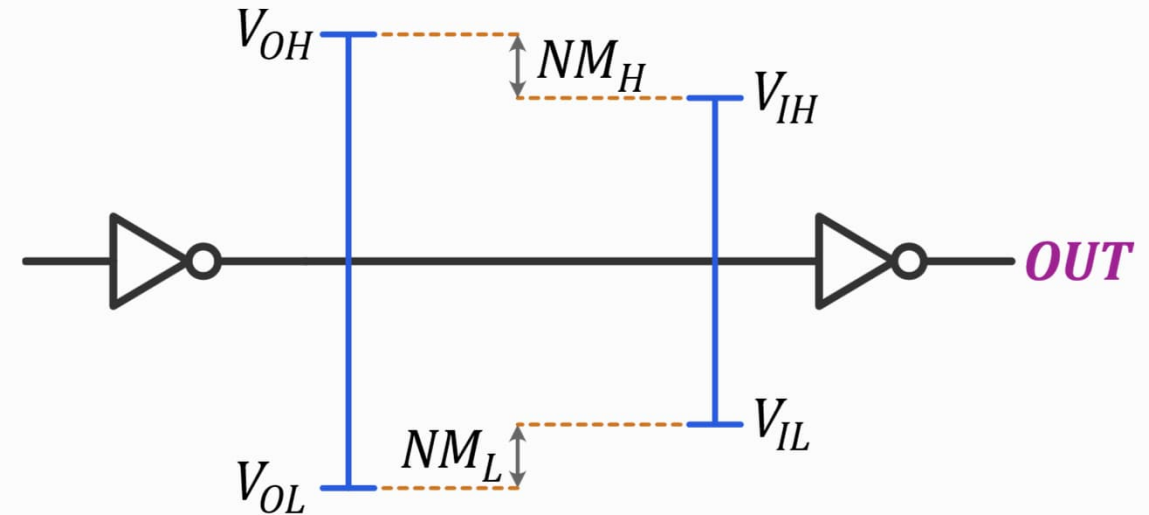


- Realistic input-output characteristics
- Low State: "0" $\equiv [0, V_{IL})$
- High State: "1" $\equiv (V_{IH}, V_{DD}]$



Noise Margin

- **Noise Margin:** Maximum tolerable noise for reliable function
- Sources of Noise:
 - Variations in manufacturing process, temperature and supply voltage (**PVT**)
 - **Radiation** waves and magnetic fields
 - Nearby (both on-chip and off-chip) **switching** circuits



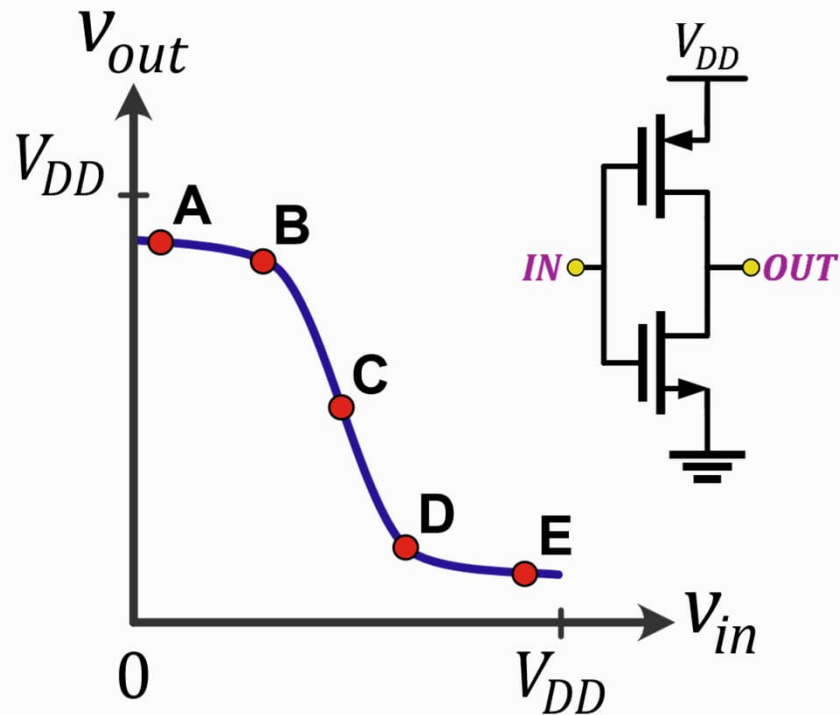
$$NM_L = V_{IL} - V_{OL}$$

$$NM_H = V_{OH} - V_{IH}$$



Pause and Ponder 2

- Could you specify the operating region (cut-off, linear, saturation) for NMOS and PMOS transistors at each point?



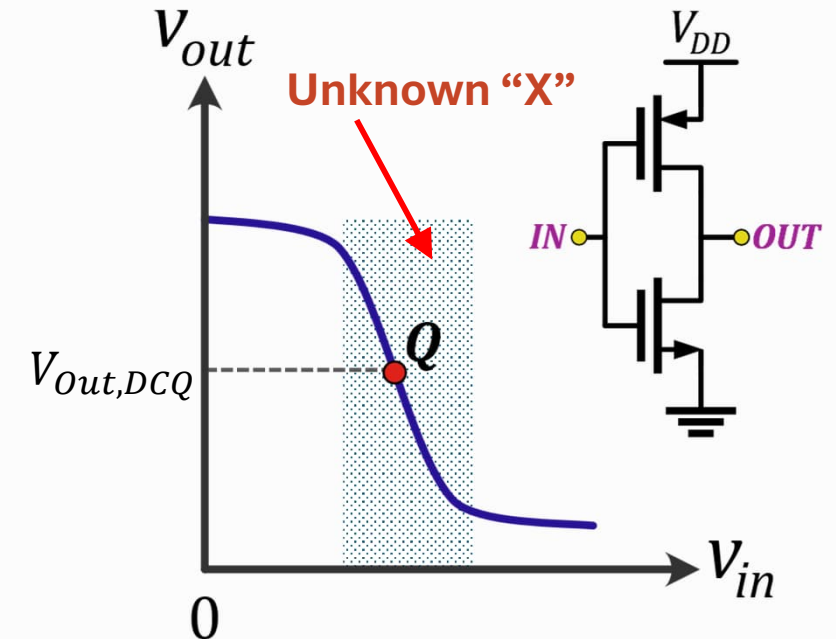
Operating Point	NMOS	PMOS
A	Cut-off	Linear
B	Saturation	Linear
C	Saturation	Saturation
D	Linear	Saturation
E	Linear	Cut-off



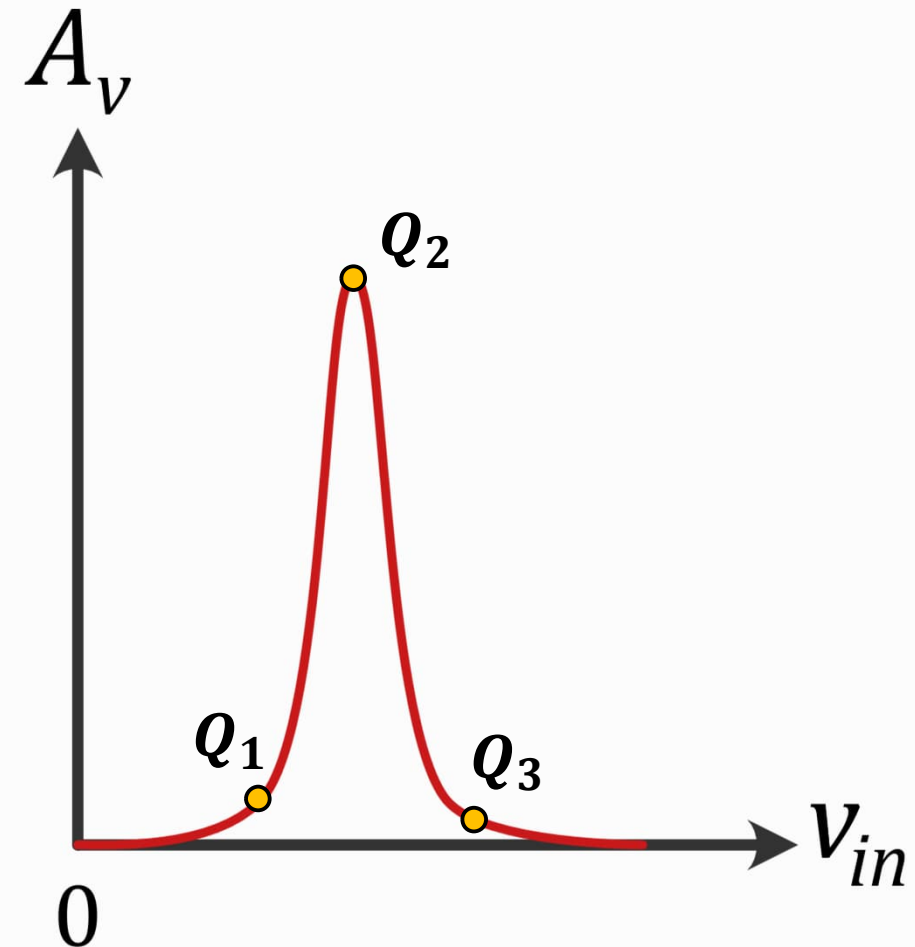
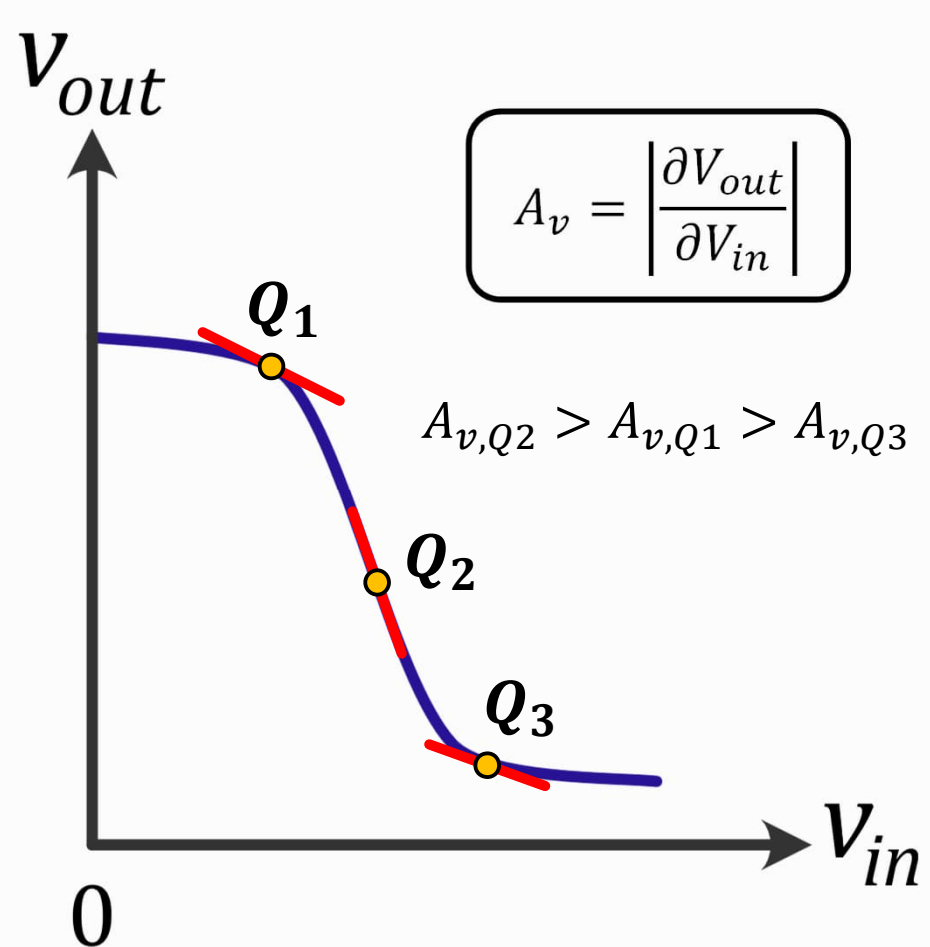
Unknown (“X”) does NOT equate to useless!

- When both transistors operate in saturation, the inverter amplifies the input signal.
- **DC Operating Point (Q):** Identified by DC operating current (i_D) and voltages (V_{DS} and V_{GS}) of each transistor.
- **Gain (A_v):** the ratio of signal amplitudes

$$\left. \begin{aligned} A_v &= \left| \frac{v_{out,sig}}{v_{in,sig}} \right| \\ v_{out,Q} &= v_{out,DCQ} + A_v v_{in,sig} \end{aligned} \right\} \Rightarrow A_v = \left| \frac{\partial v_{out}}{\partial v_{in}} \right|$$



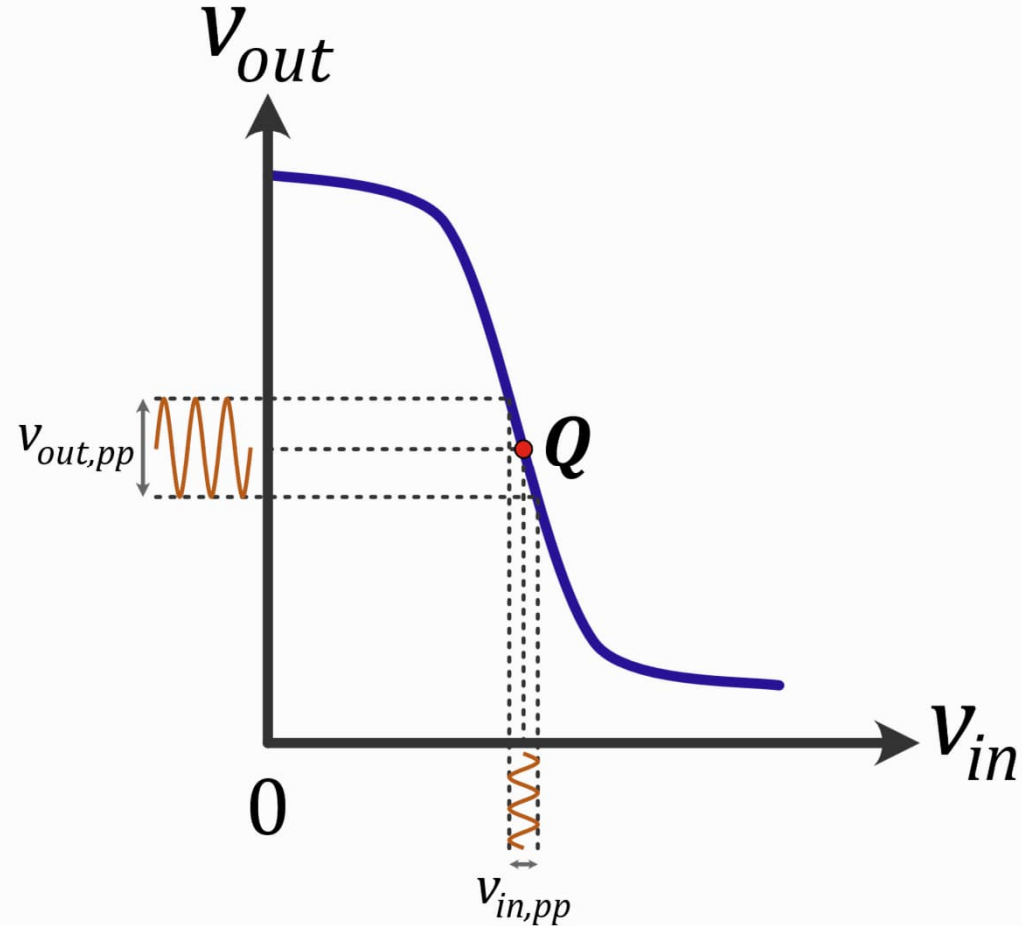
Voltage Gain



Voltage Gain (signal illustration)

- **pp**: peak-to-peak value

$$A_v = \left| \frac{v_{out,pp}}{v_{in,pp}} \right|$$



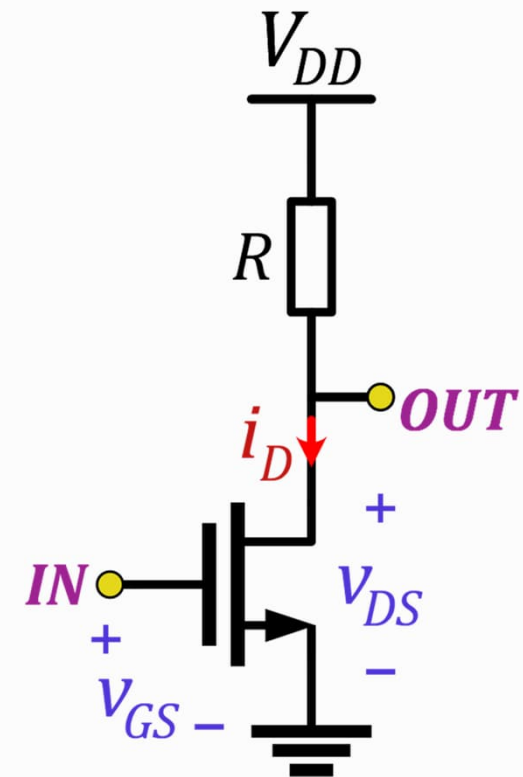
Circuit Analysis: Graphical Method

- **Step 1:** Write a linear equation for $i - v$ relationship of nonlinear device (transistor, diode, etc.)

KVL: $V_{DD} = Ri_D + v_{DS} \Rightarrow$
$$i_D = \frac{V_{DD}}{R} - \frac{v_{DS}}{R}$$

- Example: $V_{DD} = 7\text{ V}, R = 1\text{ k}\Omega$

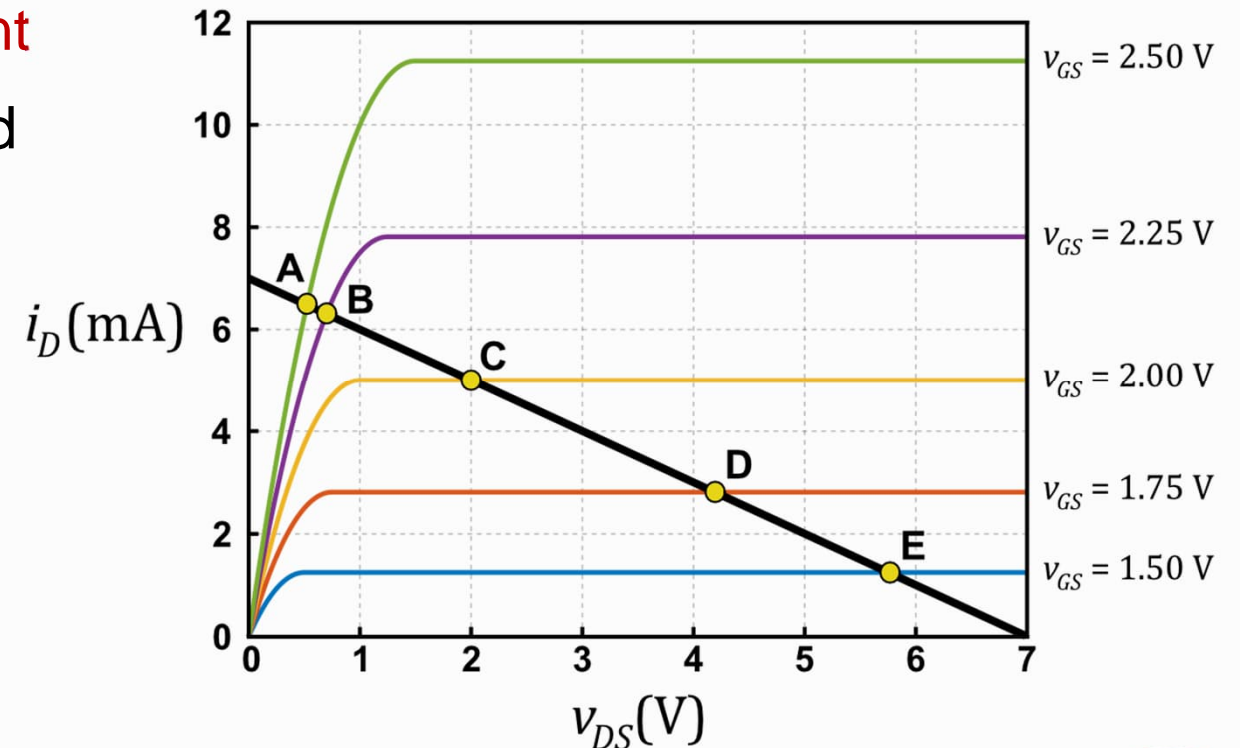
$$i_D = 7\text{ mA} - \frac{v_{DS}}{1000}$$



Circuit Analysis: Graphical Method

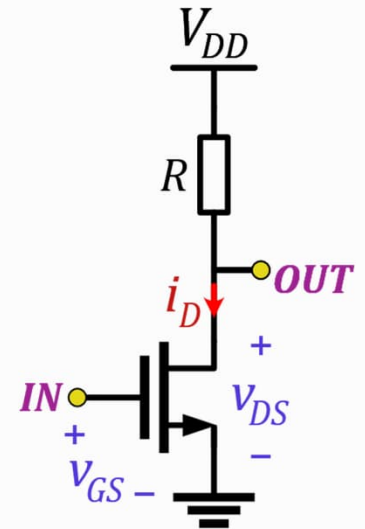
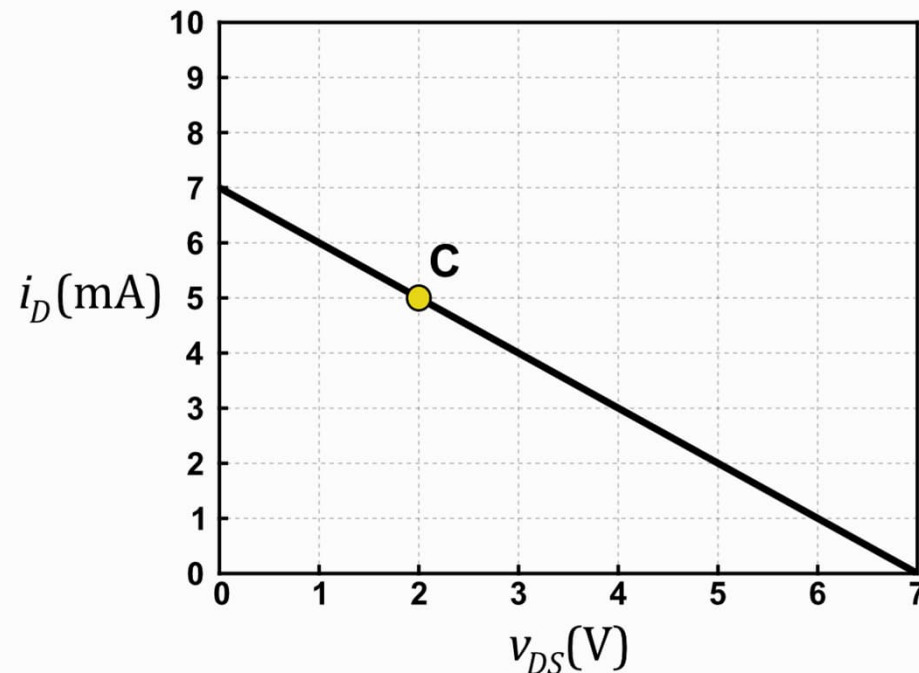
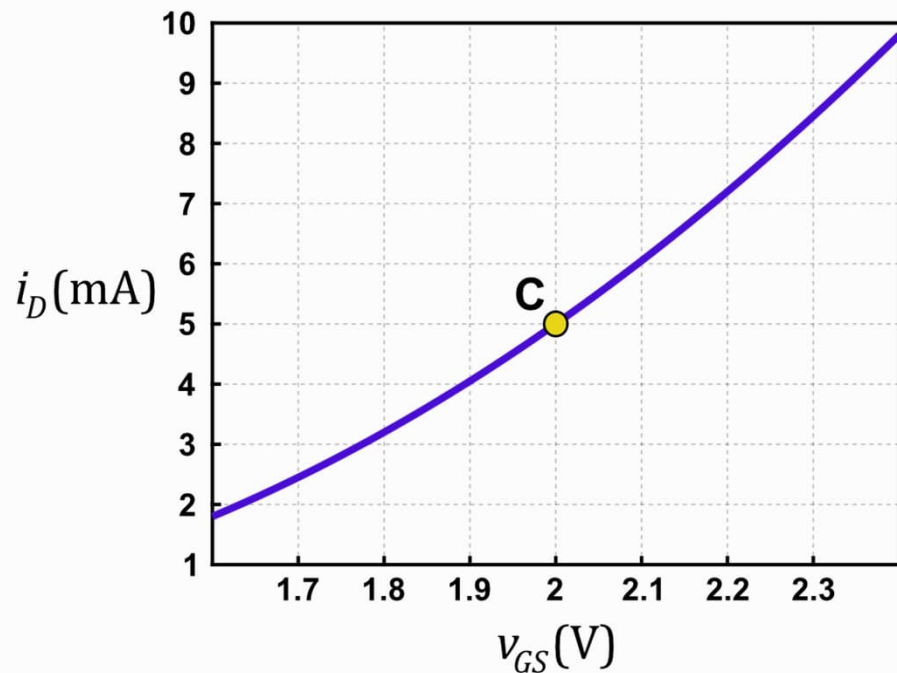
- **Step 2:** Determine **the operating point** **by intersecting** the linear function and nonlinear characteristic curves of device.
- A and B: linear region \rightarrow no gain ☹️
- C, D, and E: saturation \rightarrow 😊
- Let's pick C!

$$\rightarrow V_{GS,C} = 2 \text{ V}, V_{DS,C} = 2 \text{ V}, I_{D,C} = 5 \text{ mA}$$



Circuit Analysis: Graphical Method

- **Step 3:** Find voltage gain from $v_{in} - v_{out}$ curve.



$$v_{in} = v_{GS}$$

$$v_{out} = v_{DS}$$



Circuit Analysis: Graphical Method

